

Thermocouple EMF to Temperature Converter, ±1.5°C Maximum Accuracy

Features

- Thermocouple Electromotive Force (EMF) to °C Converter:
 - Integrated cold-junction compensation
 - Integrated thermocouple open-circuit and short-circuit detection
- Supported Types (designated by NIST ITS-90):
- Type K, J, T, N, S, E, B and R
- Sensor Accuracy for Thermocouple Hot-Junction:
 - MCP9600/01 ±0.5°C/±1.5°C (typ./max.)
 - MCP96L00/L01 ±2.0°C/±4.0°C (typ./max.)
 - MCP96RL00/RL01 ±4.0°C/±8.0°C (typ./max.)
- Measurement Resolution:
 - Hot and cold-junctions: +0.0625°C (typical)
- Four Programmable Temperature Alert Outputs:
 - Monitor hot or cold-junction temperatures
 - Detect rising or falling temperatures
 - Up to 255°C of programmable hysteresis
- Programmable Digital Filter for Temperature
- · Low Power:
 - Shutdown mode
- Burst mode: 1 to 128 temperature samples
- 2-Wire Interface: I²C Compatible, 100 kHz:
 - Supports eight devices per I²C Bus
- Operating Voltage Range: 2.7V to 5.5V
- Operating Current: 300 µA (typical)
- Shutdown Current: 2 µA (typical)
- Package: 20-Lead MQFN

Typical Applications

- Petrochemical Thermal Management
- Hand-Held Measurement Equipment
- Industrial Equipment Thermal Management
- Commercial and Industrial Ovens
- Industrial Engine Thermal Monitor
- Temperature Detection Racks

Description

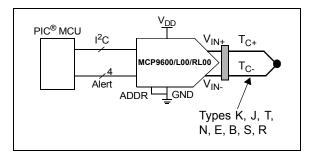
The Microchip Technology Inc. MCP960X/L0X/RL0X converts thermocouple EMF to degree Celsius with integrated cold-junction compensation. The temperature correction coefficients are derived from the National Institute of Standards and Technology (NIST) ITS-90 Thermocouple Database. The MCP9600/01 corrects the thermocouple nonlinear error characteristics of eight thermocouple types and outputs $\pm 0.5^{\circ}$ C/ $\pm 1.5^{\circ}$ C (Typ./Max.).

The MCP960X/L0X/RL0X digital temperature sensor comes with user-programmable registers which provide design flexibility for various temperature sensing applications. The registers allow user-selectable settings, such as Low-Power modes for battery powered applications, adjustable digital filter for fast transient temperatures and four individually programmable temperature alert outputs which can be used to detect multiple temperature zones.

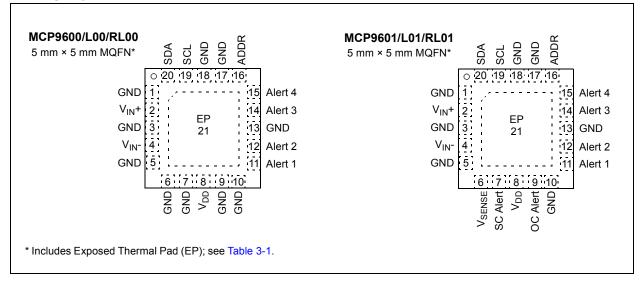
In addition, the MCP9601/L01/RL01 family provides integrated Thermocouple open-circuit and short-circuit detection features. An alert signal is asserted when the thermocouple wire is broken or disconnected. Similarly, alert signal is asserted when the Thermocouple is shorted to ground or power.

The temperature alert limits have multiple user-programmable configurations, such as alert polarity as either an active-low or active-high push-pull output, and output function as a Comparator mode (useful for thermostat-type operation) or Interrupt mode for microprocessor-based systems. In addition, the alerts can detect either a rising or a falling temperature with up to +255°C hysteresis.

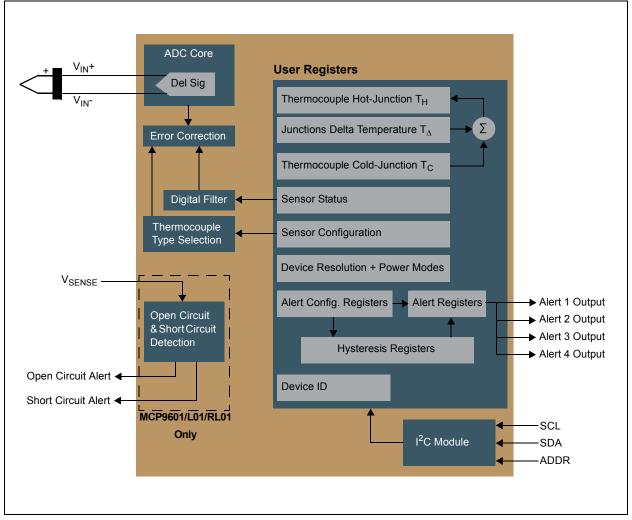
This sensor uses an industry standard 2-wire, I^2C compatible serial interface and supports up to eight devices per bus by setting the device address using the ADDR pin.



Package Types



MCP960X/L0X/RL0X Block Diagram



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1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

V _{DD}	6.0V
Voltage at All Input/Output Pins	GND – 0.3V to 6.0V
Storage Temperature	
Ambient Temperature with Power Applied	
Junction Temperature (T _J)	+150°C
ESD Protection on All Pins (HBM:MM)	
Latch-up Current at Each Pin	

† Notice: Stresses above those listed under "Maximum ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

DC CHARACTERISTICS

Electrical Specifications: Unless otherwise indicated, V_{DD} = 2.7V to 5.5V, GND = Ground, T_A = -40°C to +125°C (where: $T_A = T_C$, defined as Device Ambient Temperature).

		,				
Parameters	Sym.	Min.	Тур.	Max.	Unit	Conditions
Thermocouple Sensor Measurement Acc	curacy — I	MCP9600/	01			
T_{H} Hot-Junction Accuracy (V _{DD} = 3.3V)	T _{H_ACY}	-1.5	±0.5	+1.5	℃	$T_A = 0^{\circ}C$ to +85°C,
$T_H = T_C + T_\Delta$ (Note 1)		-3.0	±1	+3.0		$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$
T_{C} Cold-Junction Accuracy (V _{DD} = 3.3V)	T _{C_ACY}	-1.0	±0.5	+1.0	℃	$T_A = 0^{\circ}C$ to +85°C
		-2.0	±1	+2.0		$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$
T_Δ Junctions Temperature Delta Accurac	у — МСР	9600/01				
Type K: T _Δ = -200°C to +1372°C V _{EMF} Range: -5.907 mV to 54.886 mV	T_{Δ_ACY}	-0.5	±0.25	+0.5	°C	T _A = 0°C to +85°C, V _{DD} = 3.3V (Note 2)
Type J: T_{Δ} = -150°C to +1200°C V _{EMF} Range: -3.336 mV to 47.476 mV						
Type T: T_{Δ} = -200°C to +400°C V _{EMF} Range: -5.603 mV to 20.81 mV						
Type N: T _Δ = -150°C to +1300°C V _{EMF} Range: -3.336 mV to 47.476 mV						
Type E: T _Δ = -200°C to +1000°C V _{EMF} Range: -8.825 mV to 76.298 mV						
Type S: T _Δ = 250°C to +1664°C V _{EMF} Range: -1.875 mV to 17.529 mV						$T_A = 0^{\circ}C \text{ to } +85^{\circ}C,$ $V_{DD} = 3.3V$
Type B: T _Δ = 1000°C to +1800°C V _{EMF} Range: -4.834 mV to 13.591 mV						(Notes 2, Note 3)
Type R: T _Δ = 250°C to +1664°C V _{EMF} Range: -1.923 mV to 19.732 mV						

Note 1 The T_C and T_{Δ} summation is implemented in milli-volt (mV) domain. The result, T_H (mV), is converted to Degree Celsius using the NIST ITS-90 Conversion database.

2 The T_{Δ_ACY} temperature accuracy specification is defined as the device accuracy to the NIST ITS-90 Thermocouple EMF to Degree Celsius Conversion Database. T_{Δ} is also defined as the temperature difference between the hot and cold-junctions or temperatures from the NIST ITS-90 database with $T_{C} = 0^{\circ}C$.

3 The device measures temperature below the specified range, however, the sensitivity to changes in temperature reduces exponentially. Type R and S measure down to -50°C, or -0.226 mV_{EMF} and -0.235 mV_{EMF}, respectively. Type B measures down to 500°C or 1.242 mV_{EMF} (see Figures 2-7, 2-8, 2-10, 2-11, 2-14 and 2-17).

4 Exceeding the V_{IN_CM} input range may cause leakage current through the ESD protection diodes at the thermocouple input pins. This parameter is characterized but not production tested.

Electrical Specifications: Unless otherwise indicated, V_{DD} = 2.7V to 5.5V, GND = Ground, T_A = -40°C to +125°C (where: $T_A = T_C$, defined as Device Ambient Temperature).

				1		1
Parameters	Sym.	Min.	Тур.	Max.	Unit	Conditions
Thermocouple Sensor Measurement Acc	curacy — I	MCP96L00	0/L01	•		1
T_{H} Hot-Junction Accuracy (V _{DD} = 3.3V)	T _{H_ACY}	-4.0	±2	+4.0	°C	$T_A = 0^{\circ}C$ to +85°C,
$T_{H} = T_{C} + T_{\Delta} $ (Note 1)		-6.0	±4	+6.0		$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$
T_{C} Cold-Junction Accuracy (V _{DD} = 3.3V)	T _{C_ACY}	-1.0	±0.5	+1.0	°C	$T_A = 0^{\circ}C \text{ to } +85^{\circ}C$
		-2.0	±1	+2.0		$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$
T_Δ Junctions Temperature Delta Accurac	су — МСР	96L00/L01				
Type K: T _Δ = -200°C to +1372°C V _{EMF} Range: -5.907 mV to 54.886 mV	T_{Δ_ACY}	-3.0	±1.5	+3.0	°C	T _A = 0°C to +85°C, V _{DD} = 3.3V (Note 2)
Type J: T_{Δ} = -150°C to +1200°C V _{EMF} Range: -3.336 mV to 47.476 mV						
Type T: T _Δ = -200°C to +400°C V _{EMF} Range: -5.603 mV to 20.81 mV						
Type N: T _Δ = -150°C to +1300°C V _{EMF} Range: -3.336 mV to 47.476 mV						
Type E: Τ _Δ = -200°C to +1000°C V _{EMF} Range: -8.825 mV to 76.298 mV						
Type S: T _Δ = 250°C to +1664°C V _{EMF} Range: -1.875 mV to 17.529 mV						$T_A = 0^{\circ}C \text{ to } +85^{\circ}C,$ $V_{DD} = 3.3V$
Type B: T _Δ = 1000°C to +1800°C V _{EMF} Range: -4.834 mV to 13.591 mV						(Notes 2, Note 3)
Type R: T _Δ = 250°C to +1664°C V _{EMF} Range: -1.923 mV to 19.732 mV						

Note 1 The T_C and T_{Δ} summation is implemented in milli-volt (mV) domain. The result, T_H (mV), is converted to Degree Celsius using the NIST ITS-90 Conversion database.

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- 4 Exceeding the V_{IN_CM} input range may cause leakage current through the ESD protection diodes at the thermocouple input pins. This parameter is characterized but not production tested.

Electrical Specifications: Unless otherwise indicated, V_{DD} = 2.7V to 5.5V, GND = Ground, T_A = -40°C to +125°C (where: $T_A = T_C$, defined as Device Ambient Temperature).

(where: $T_A = T_C$, defined as Device 7 (indefined)		,	1	1	T	1
Parameters	Sym.	Min.	Тур.	Max.	Unit	Conditions
Thermocouple Sensor Measurement Acc	curacy — I	MCP96RL	00/01		•	
T_{H} Hot-Junction Accuracy (V_{DD} = 3.3V)	T _{H_ACY}	-8.0	±4	+8.0	°C	$T_A = 0^{\circ}C$ to +85°C,
$T_{H} = T_{C} + T_{\Delta} (Note 1)$		-10.0	±6	+10.0		$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$
T_{C} Cold-Junction Accuracy (V _{DD} = 3.3V)	T _{C_ACY}	-2.0	±1	+2.0	°C	$T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$
T_{Δ} Junctions Temperature Delta Accurac	су — МСР	96RL00/01				
Type K: T _Δ = -200°C to +1372°C V _{EMF} Range: -5.907 mV to 54.886 mV	T_{Δ_ACY}	-6.0	±3.0	+6.0	°C	$T_A = 0^{\circ}C \text{ to } +85^{\circ}C,$ $V_{DD} = 3.3V (Note 2)$
Type J: T _Δ = -150°C to +1200°C V _{EMF} Range: -3.336 mV to 47.476 mV						
Type T: T _Δ = -200°C to +400°C V _{EMF} Range: -5.603 mV to 20.81 mV						
Type N: T _Δ = -150°C to +1300°C V _{EMF} Range: -3.336 mV to 47.476 mV						
Type E: T _Δ = -200°C to +1000°C V _{EMF} Range: -8.825 mV to 76.298 mV	-					
Type S: T _A = 250°C to +1664°C V _{EMF} Range: -1.875 mV to 17.529 mV	-					$T_A = 0^{\circ}C \text{ to } +85^{\circ}C,$ $V_{DD} = 3.3V$
Type B: T _Δ = 1000°C to +1800°C V _{EMF} Range: -4.834 mV to 13.591 mV						(Notes 2, Note 3)
Type R: T_{Δ} = 250°C to +1664°C V _{EMF} Range: -1.923 mV to 19.732 mV						

Note 1 The T_C and T_{Δ} summation is implemented in milli-volt (mV) domain. The result, T_H (mV), is converted to Degree Celsius using the NIST ITS-90 Conversion database.

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Electrical Specifications: Unless otherwise indicated, V_{DD} = 2.7V to 5.5V, GND = Ground, T_A = -40°C to +125°C (where: T_A = T_C , defined as Device Ambient Temperature).

Parameters	Sym.	Min.	Тур.	Max.	Unit	Conditions
Sensor Characteristics						
T_{C} and T_{H} Temperature Resolution	T _{RES}	—	±0.0625	—	°C	With max. resolution
Sampling Rate (T _A = +25°C)	t _{CONV}		320			18-bit resolution
		_	80	_	ms	16-bit resolution
		—	20	_	1115	14-bit resolution
		_	5	_		12-bit resolution
Temperature Calculation Time	t _{CALC}	_	12	_	ms	T _A = +25°C
Thermocouple Input						
Offset Error	V _{OERR}	—	±2	_	μV	
Offset Error Drift	V_{OE_DR}	—	50	_	nV/°C	
Full-Scale Gain Error — MCP9600/01	G _{ERR}	—	—	±0.04		$T_A = 0^{\circ}C$ to +85°C
Full-Scale Gain Error — MCP96L00/L01		_	±0.12	_	%FS	$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$
Full-Scale Gain Error — MCP96RL00/RL01		_	±0.24	_		
Full-Scale Gain Error Drift	G_{ER_DR}	—	±0.01	—	%FS	
Full-Scale Integral Nonlinearity	INL	—	10	—	ppm	
Voltage Resolution	V _{RES}	—	2	_	μV	18-bit resolution
Differential Mode Range	$V_{IN_{DF}}$	-250	_	+250	mV	ADC input range
Differential Mode Impedance	Z _{IN_DF}	—	300	—	kΩ	
Common-Mode Range	V _{IN_CM}	V _{DD} -0.3	—	V _{DD} + 0.3	V	(Note 4)
Common-Mode Impedance	Z _{IN_CM}	—	25	—	MΩ	
Common-Mode Rejection Ratio	CMRR	—	105	—	dB	
Power Supply Rejection Ratio	PSRR	_	60	_	dB	
Line Regulation	V _{Line_R}	—	0.2		°C/V	
Voltage Sense Input (VSENSE) for Thern	nocouple	Open and S	Short-Circ	cuit Detect	ion (MC	P9601/L01/RL01)
V _{SENSE} Input Range	V _{SiRNG}	0	—	100		(see Figure 1-1)
- Range: Short Circuit to V _{DD}	V _{SiSC}	90	_	100		SC Alert asserts
- Range: Short Circuit to GND		0		10	%V _{DD}	
- Range: Open Circuit	V _{SiOC}	58	_	75	20	OC Alert asserts
- Range: Normal Operation	V _{SiNOR}	40		58		OC Alert deasserts

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4 Exceeding the V_{IN_CM} input range may cause leakage current through the ESD protection diodes at the thermocouple input pins. This parameter is characterized but not production tested.

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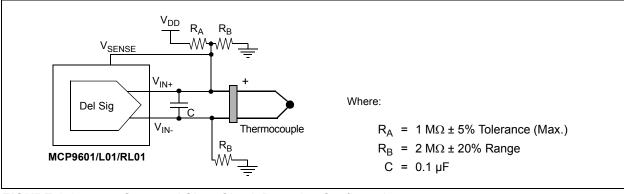
Parameters	Sym.	Min.	Тур.	Max.	Unit	Conditions	
V _{SENSE} Input Leakage	I _{SiLEAK}		0.1	1	μA		
Alert 1, 2, 3, 4 Outputs, SC Alert and OC	Alert Out	puts (MCP9	601/L01/	RL01)	1		
Low-Level Voltage	V _{OL}	—		0.4	V	I _{OL} = 3 mA	
High-Level Voltage	V _{OH}	$V_{DD} - 0.5$		—	V	I _{OH} = 3 mA	
Operating Voltage and Current	•	·		•	•		
Operating Voltage	V _{DD}	2.7		5.5	V		
I ² C Inactive Current	I _{DD}	—	0.3	0.5	mA	$V_{DD} = 3.3V,$	
I ² C Active Current or During t _{CALC}		—	1.5	2.5	mA	T _A = +85°C	
Shutdown Current	I _{SHDN}	—	2	5	μA	I ² C inactive, T _A = +85°C	
Power-on Reset (POR) Thresholds	V _{POR}	1.0	2.1	2.6	V	Rising/Falling V _{DD}	
Thermal Response							
Package Thermal Response (Time to 63% of Final Temperature)	t _{RSP}	—	3		S	+25°C (air) to +125 (oil bath), 2x2" PC	

Note 1 The T_C and T_{Δ} summation is implemented in milli-volt (mV) domain. The result, T_H (mV), is converted to Degree Celsius using the NIST ITS-90 Conversion database.

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Open and Short Circuit Detection Configuration.

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INPUT/OUTPUT PIN DC CHARACTERISTICS

Electrical Specifications: Unless other	arwisa indi	cated $V_{ac} = 1$	2 7\/ to 5 5\/ CN	ID = Ground T	= _40°	°C to +125°C
	Electrical Specifications: Unless otherwise indicated, V_{DD} = 2.7V to 5.5V, GND = Ground, T_A = -40°C to +125°C (where: T_A = T_C , defined as Device Ambient Temperature).					
Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions
Serial Input/Output and I ² C Slave Ac	ldress Inp	out (ADDR)				
Input (SCL, SDA, ADDR)						
High-Level Voltage	V _{IH}	$0.7 \times V_{DD}$		_	V	
Low-Level Voltage	V _{IL}			$0.3 \times V_{DD}$	V	
Input Current	I _{LEAK}			±2	μA	
Hysteresis	V _{HYST}		0.05 × V _{DD}	—	V	V _{DD} > 2V
Spike Suppression	T _{SP}		50	—	ns	
Output (SDA)						
Low-Level Voltage	V _{OL}		_	0.4	V	I _{OL} = 3 mA
High-Level Current (leakage)	I _{OH}			1	μA	$V_{OH} = V_{DD}$
Low-Level Current	I _{OL}	6	_	—	mA	V _{OL} = 0.6V
Capacitance	C _{IN}	—	5	—	pF	
I ² C Slave Address Selection Levels	(Note 1)					
Command Byte [1100 000x]	V _{ADDR}	GND	_	—	V	Address = 0
Command Byte [1100 001x]		V _{ADDR_L}	V _{ADDR_TYP}	V _{ADDR_H}		Address = 1
Command Byte [1100 010x]						Address = 2
Command Byte [1100 011x]		(Note 2)	(Note 2)	(Note 2)		Address = 3
Command Byte [1100 100x]						Address = 4
Command Byte [1100 101x]						Address = 5
Command Byte [1100 110x]						Address = 6
Command Byte [1100 111x]		_		V _{DD}		Address = 7

Note 1 The ADDR pin can be tied to V_{DD} or V_{SS} . For additional slave addresses, a resistive divider network can be used to set voltage levels that are rationed to V_{DD} . The device supports up to eight levels (see Section 6.3.1 "I²C Addressing" for recommended resistor values).

 $\begin{array}{ll} \textbf{2} & V_{ADDR_TYP} = Address * V_{DD}/8 + V_{DD}/16, \\ & V_{ADDR_L} = V_{ADDR_TYP} - V_{DD}/32 \text{ and} \\ & V_{ADDR_H} = V_{ADDR_TYP} + V_{DD}/32 \text{ (where: Address = 1, 2, 3, 4, 5, 6).} \end{array}$

TEMPERATURE CHARACTERISTICS

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions
Temperature Ranges						
Specified Temperature Range	T _A	-40	_	+125	°C	(Note 1)
Operating Temperature Range	T _A	-40	_	+125	°C	
Storage Temperature Range	T _A	-65	_	+150	°C	
Thermal Package Resistances						
Thermal Resistance, MQFN	θ _{JA}	_	38.8		°C/W	

Note 1 Operation in this range must not cause T_J to exceed the Maximum Junction Temperature (+150°C).

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SENSOR SERIAL INTERFACE TIMING SPECIFICATIONS

Electrical Specifications: Unless otherwise indicated, GND = Ground, $T_A = -40^{\circ}C$ to $+125^{\circ}C$, $V_{DD} = 2.7V$ to 5.5V and $C_I = 80$ pF (Note 1).

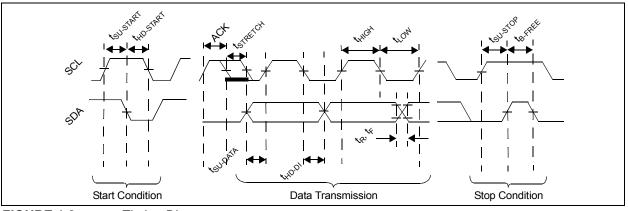
Parameters	Sym.	Min.	Max.	Units
2-Wire I ² C Interface				
Serial Port Frequency	f _{SCL}	10	100	kHz
Low Clock (Note 2)	t _{LOW}	4700	—	ns
High Clock	t _{HIGH}	4000	—	ns
Rise Time (Note 3)	t _R	—	1000	ns
Fall Time (Note 3)	t _F	20	300	ns
Data in Setup Time (Note 2)	t _{SU:DAT}	250	—	ns
Data in Hold Time	t _{HD:DAT}	0	—	ns
Start Condition Setup Time	t _{SU:STA}	4700	—	ns
Start Condition Hold Time	t _{HD:STA}	4000	—	ns
Stop Condition Setup Time	t _{SU:STO}	4000	—	ns
Bus Idle/Free	t _{B-FREE}	10	—	μs
Bus Capacitive Load	Cb	—	400	pf
Clock Stretching (Note 4)	t _{STRETCH}	60	—	μs

Note 1 All values referred to $V_{IL\ MAX}$ and $V_{IH\ MIN}$ levels.

2 This device can be used in a Standard mode I²C bus system, but the requirement, $t_{SU:DAT} \ge 250$ ns, must be met.

3 Characterized, but not production tested.

4 Master controllers without features to detect clock stretching by Slave devices, should reduce f_{SCL} for proper I²C communication for Read commands. See Figure 2-29 for a typical t_{STRETCH} performance.





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2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

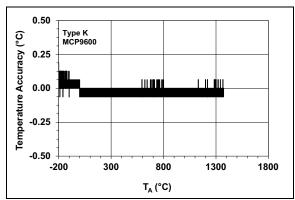


FIGURE 2-1: Typical Temperature Accuracy from NIST ITS-90 Database, Type K.

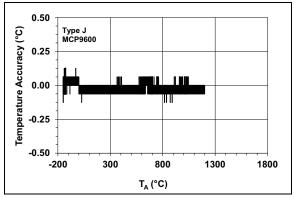


FIGURE 2-2: Typical Temperature Accuracy from NIST ITS-90 Database, Type J.

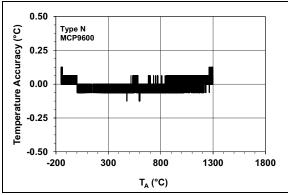


FIGURE 2-3: Typical Temperature Accuracy from NIST ITS-90 Database, Type N.

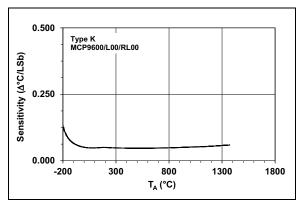


FIGURE 2-4: Temperature Sensitivity with 18-Bit Resolution, Type K.

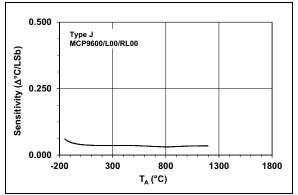


FIGURE 2-5: Temperature Sensitivity with 18-Bit Resolution, Type J.

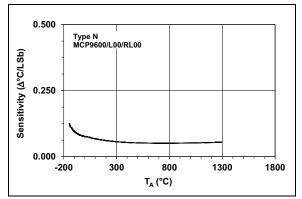


FIGURE 2-6: Temperature Sensitivity with 18-Bit Resolution, Type N.

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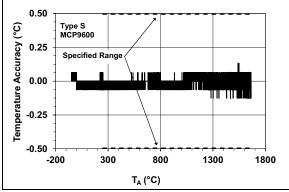


FIGURE 2-7: Typical Temperature Accuracy from NIST ITS-90 Database, Type S.

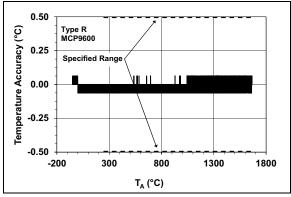


FIGURE 2-8: Typical Temperature Accuracy from NIST ITS-90 Database, Type R.

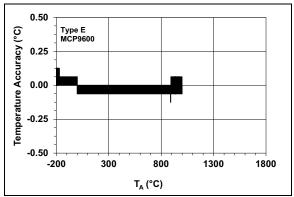


FIGURE 2-9: Typical Temperature Accuracy from NIST ITS-90 Database, Type E.

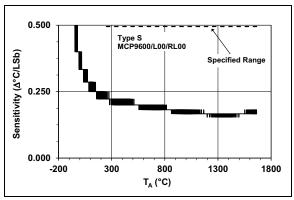


FIGURE 2-10: Temperature Sensitivity with 18-Bit Resolution, Type S.

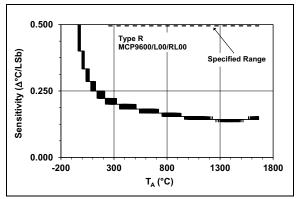


FIGURE 2-11: Temperature Sensitivity with 18-Bit Resolution, Type R.

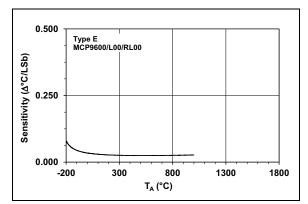


FIGURE 2-12: Temperature Sensitivity with 18-Bit Resolution, Type E.

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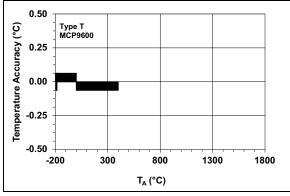


FIGURE 2-13: Typical Temperature Accuracy from NIST ITS-90 Database, Type T.

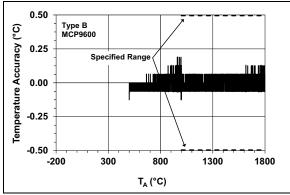


FIGURE 2-14: Typical Temperature Accuracy from NIST ITS-90 Database, Type B.

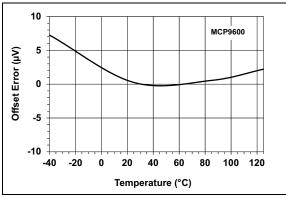


FIGURE 2-15: Input Offset Error Voltage (V_{IN+}, V_{IN-}) .

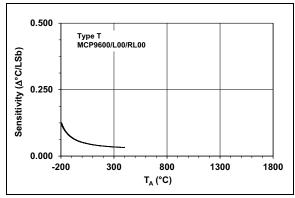


FIGURE 2-16: Temperature Sensitivity with 18-Bit Resolution, Type T.

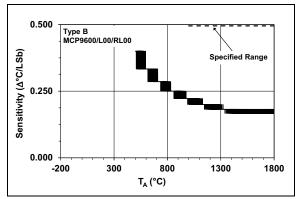


FIGURE 2-17: Temperature Sensitivity with 18-Bit Resolution, Type B.

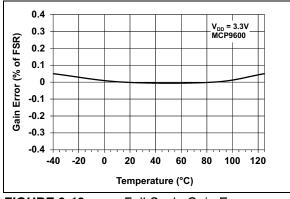
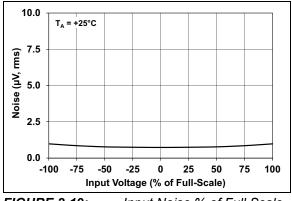
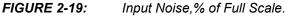


FIGURE 2-18: Full-Scale Gain Error.

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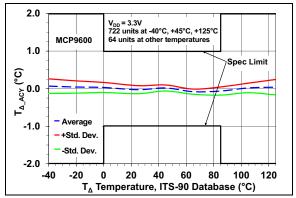
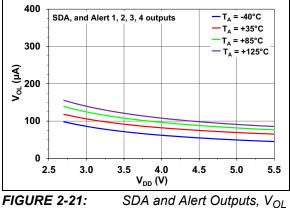
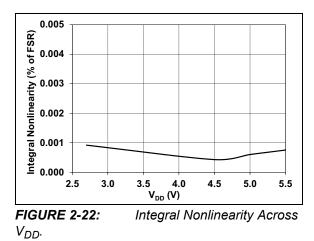


FIGURE 2-20: Cold-Junction Sensor Temperature Accuracy.



Across V_{DD}.



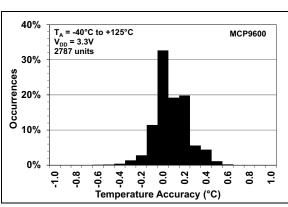
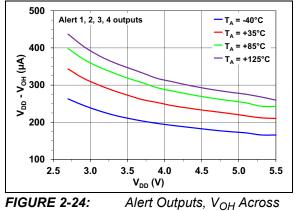
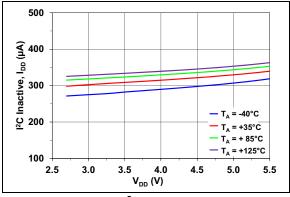


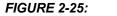
FIGURE 2-23: Cold-Junction Sensor Temperature Accuracy Distribution.

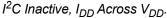


V_{DD}.

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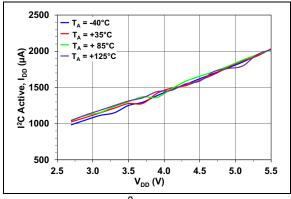


FIGURE 2-26:

 I^2C Active, I_{DD} Across V_{DD} .

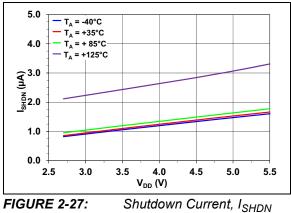
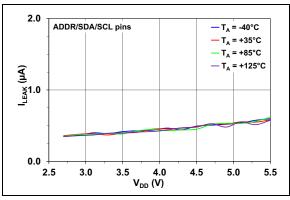
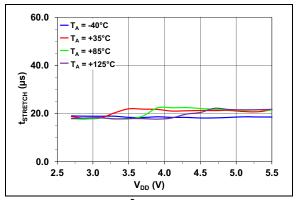


FIGURE 2-27: Across V_{DD}.



SDA, SCL and ADDR Input **FIGURE 2-28:** Pins Leakage Current, ILEAK Across VDD.



I²C Interface Clock Stretch **FIGURE 2-29:** Duration, t_{STRETCH} Across V_{DD}.

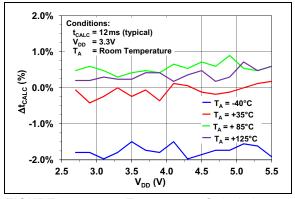


FIGURE 2-30: Temperature Calculation Duration, t_{CALC} Change Across V_{DD}.

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3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 5-1. FIN	TUNCTION TABLE		
MCP9600/L00/RL00	MCP9601/L01/RL01	Symbol	Pin Function
1, 3, 5,13, 17	1, 3, 5, 13, 17	GND	Electrical Ground
2	2	V _{IN+}	Thermocouple Positive Terminal Input
4	4	V _{IN-}	Thermocouple Negative Terminal Input
6, 7, 9, 10, 18	10, 18	GND	Not Electrical Ground; must be tied to Ground
—	6	V _{SENSE}	Thermocouple Open and Short Circuit detection input
—	7	SC Alert	Thermocouple Short Circuit Alert Output
8	8	V _{DD}	Power
—	9	OC Alert	Thermocouple Open Circuit Alert Output
11	11	Alert 1	Alert Output 1
12	12	Alert 2	Alert Output 2
14	14	Alert 3	Alert Output 3
15	15	Alert 4	Alert Output 4
16	16	ADDR	I ² C Save Address Selection Voltage Input
19	19	SCL	I ² C Clock Input
20	20	SDA	I ² C Data Input
21	21	EP	Exposed Thermal Pad (EP); must be connected to GND

TABLE 3-1: PIN FUNCTION TABLE

3.1 Ground Pin (GND)

The GND pin is the system ground pin. Pins 1, 3, 5, 13 and 17 are system ground pins and they are at the same potential. However, pins 6, 7, 9, 10 and 18 must be connected to ground for normal operation.

3.2 Thermocouple Input (V_{IN+}, V_{IN-})

The thermocouple wires are directly connected to these inputs. The positive node is connected to the $V_{\rm IN+}$ pin, while the negative node connects to the $V_{\rm IN-}$ node. The thermocouple voltage is converted to degree Celsius.

3.3 Power Pin (V_{DD})

 V_{DD} is the power pin. The operating voltage range, as specified in the DC Characteristics table, is applied on this pin.

3.4 Push-Pull Alert Outputs (Alert 1, 2, 3, 4 and OC/SC Alert)

The Alert pins are user-programmable push-pull outputs which can be used to detect rising or falling temperatures. The device outputs signal when the ambient temperature exceeds the user-programmed temperature alert limit.

The OC Alert and the SC Alert outputs are also active-high push-pull outputs (MCP9601/L01/RL01). These outputs are asserted when Open-Circuit and Short-Circuit conditions are detected on the V_{SENSE} pin.

3.5 I²C Slave Address Pin (ADDR)

This pin is used to set the I^2C slave address. This pin can be tied to V_{DD} , GND, or a ratio of V_{DD} can be selected to set up to eight address levels using a resistive voltage divider network.

3.6 Serial Clock Line (SCL)

The SCL is a clock input pin. All communication and timing is relative to the signal on this pin. The clock is generated by the host or master controller on the bus (see Section 4.0 "Serial Communication").

3.7 Serial Data Line (SDA)

SDA is a bidirectional input/output pin used to serially transmit data to/from the host controller. This pin requires a pull-up resistor (see Section 4.0 "Serial Communication").

3.8 Thermocouple Open/Short Detection Input (V_{SENSE})

The V_{SENSE} pin is a thermocouple detection input pin (MCP9601/L01/RL01) and the voltage level on this pin is used to determine whether the thermocouple is operating normally, shorted to V_{DD}/V_{SS} , or it is disconnected from the V_{IN+} and V_{IN-} pins (see Figure 1-1).

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4.0 SERIAL COMMUNICATION

4.1 2-Wire Standard Mode I²C Protocol-Compatible Interface

The MCP960X/L0X/RL0X Serial Clock Input (SCL) and the bidirectional Serial Data Line (SDA) form a 2-wire bidirectional data communication line (refer to the **Input/Output Pin DC Characteristics** table and **Sensor Serial Interface Timing Specifications** table).

The following bus protocol has been defined:

TABLE 4-1: MCP9600/L00/RL00 SERIAL BUS PROTOCOL DESCRIPTIONS

Term	Description
Master	The device that controls the serial bus, typically a microcontroller
Slave	The device addressed by the master, such as the MCP960X/L0X/RL0X
Transmitter	Device sending data to the bus
Receiver	Device receiving data from the bus
START	A unique signal from master to initiate serial interface with a slave
STOP	A unique signal from the master to terminate serial interface from a slave
Read/Write	A read or write to the MCP960X/L0X/RL0X registers
ACK	A receiver Acknowledges (ACK) the reception of each byte by polling the bus
NAK	A receiver Not Acknowledges (NAK) or releases the bus to show End-of-Data (EOD)
Busy	Communication is not possible because the bus is in use
Not Busy	The bus is in the Idle state, both SDA and SCL remain high
Data Valid	SDA must remain stable before SCL becomes high in order for a data bit to be considered valid. During normal data transfers, SDA only changes state while SCL is low.

4.1.1 DATA TRANSFER

Data transfers are initiated by a Start condition (START), followed by a 7-bit device address and a read/write bit. An Acknowledge (ACK) from the slave confirms the reception of each byte. Each access must be terminated by a Stop condition (STOP).

Repeated communication is initiated after t_{B-FREE} .

This device supports the Receive Protocol. The register can be specified using the pointer for the initial read. Each repeated read or receive begins with a Start condition and address byte. The MCP960X/L0X/RL0X retains the previously selected register. Therefore, it outputs data from the previously-specified register (repeated pointer specification is not necessary).

4.1.2 MASTER/SLAVE

The bus is controlled by a master device (typically a microcontroller) that controls the bus access, and generates the Start and Stop conditions. The MCP960X/L0X/RL0X is a slave device and does not control other devices in the bus. Both master and slave devices can operate as either transmitter or receiver. However, the master device determines which mode is activated.

4.1.3 START/STOP CONDITION

A high-to-low transition of the SDA line (while SCL is high) is the Start condition. All data transfers must be preceded by a Start condition from the master. A low-to-high transition of the SDA line (while SCL is high) signifies a Stop condition.

If a Start or Stop condition is introduced during data transmission, the MCP960X/L0X/RL0X releases the bus. All data transfers are ended by a Stop condition from the master.

4.1.4 ADDRESS BYTE

Following the Start condition, the host must transmit an 8-bit address byte to the MCP960X/L0X/RL0X. The address for the MCP960X/L0X/RL0X temperature sensor is '11, 0, 0, A2, A1, A0' in binary, where the A2, A1 and A0 bits are set externally by connecting the corresponding V_{ADDR} voltage levels on the ADDR pin (see the **"Input/Output Pin DC Characteristics"** section). The 7-bit address transmitted in the serial bit stream must match the selected address for the MCP960X/L0X/RL0X to respond with an ACK. Bit 8 in the address byte is a read/write bit. Setting this bit to '1' commands a read operation, while '0' commands a write operation (see Figure 4-1).

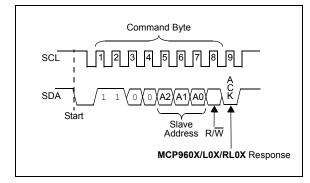


FIGURE 4-1:

Device Addressing.

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4.1.5 DATA VALID

After the Start condition, each bit of data in transmission needs to be settled for a time specified by $t_{SU-DATA}$ before SCL toggles from low-to-high (see the **"Sensor Serial Interface Timing Specifications"** section).

4.1.6 ACKNOWLEDGE (ACK/NAK)

Each receiving device, when addressed, is expected to generate an ACK bit after the reception of each byte. The master device must generate an extra clock pulse for ACK to be recognized.

The Acknowledging device pulls down the SDA line for $t_{SU-DATA}$ before the low-to-high transition of SCL from the master. SDA also needs to remain pulled down for t_{HD-DAT} after a high-to-low transition of SCL.

During read, the master must signal an End-of-Data (EOD) to the slave by not generating an ACK bit (NAK) once the last bit has been clocked out of the slave. In this case, the slave will leave the data line released to enable the master to generate the Stop condition.

4.1.7 CLOCK STRETCHING

During the I^2C read operation, this device will hold the I^2C clock line low for t_{STRECH} after the falling edge of the ACK signal. In order to prevent bus contention, the master controller must release or hold the SCL line low during this period.

Note:	If the master controller does not provide						
	the adequate delay as specified by						
	t _{STRECH} , then the device will output the previously transmitted data.						

In addition, the master controller must provide eight consecutive clock cycles after generating the ACK bit from a read command. This allows the device to push out data from the SDA Output Shift registers. Missing clock cycles could result in bus contention. At the end of one or more data transmission, the master controller must provide the NAK bit, followed by a Stop Condition to terminate communication (see Figure 4-3).

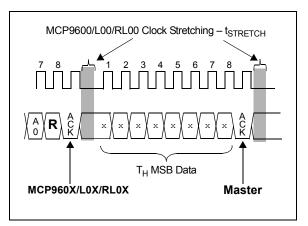
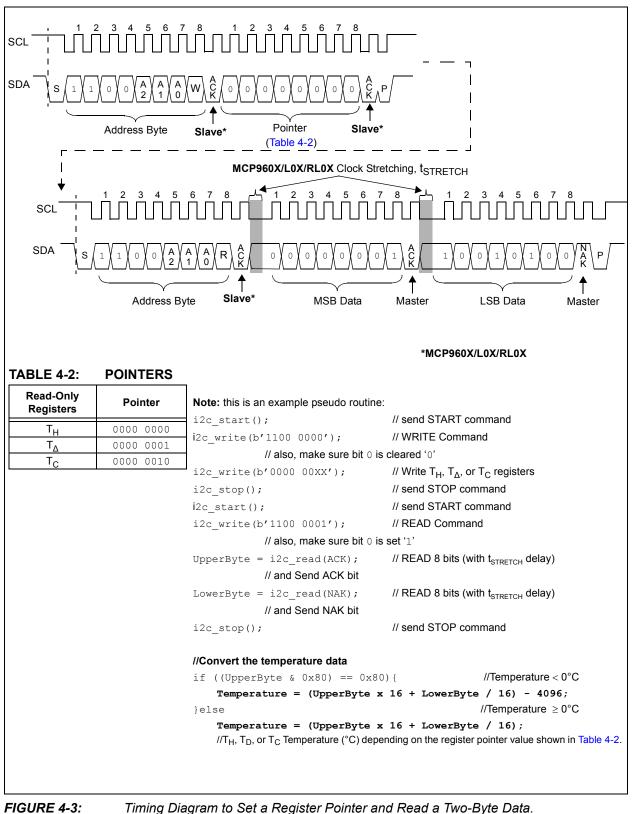


FIGURE 4-2: Clock Stretching.

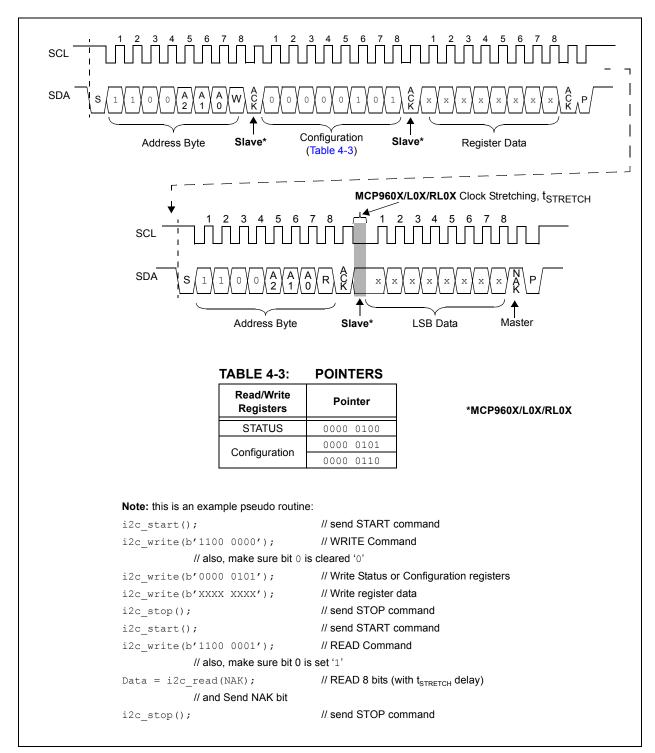
4.1.8 SEQUENTIAL READ

During a sequential read, the device transmits data bytes starting from the previously set Register Pointer. The MCP960X/L0X/RL0X increments an internal address pointer each time a byte transmission is successfully completed with an ACK bit from the master controller. Therefore, the device can sequentially output the entire register values shown in Table 5-1 (see Figure 4-6). A Stop Condition terminates the sequential read.

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Timing Diagram to Set a Register Pointer, Write One Byte, and Read the Data.

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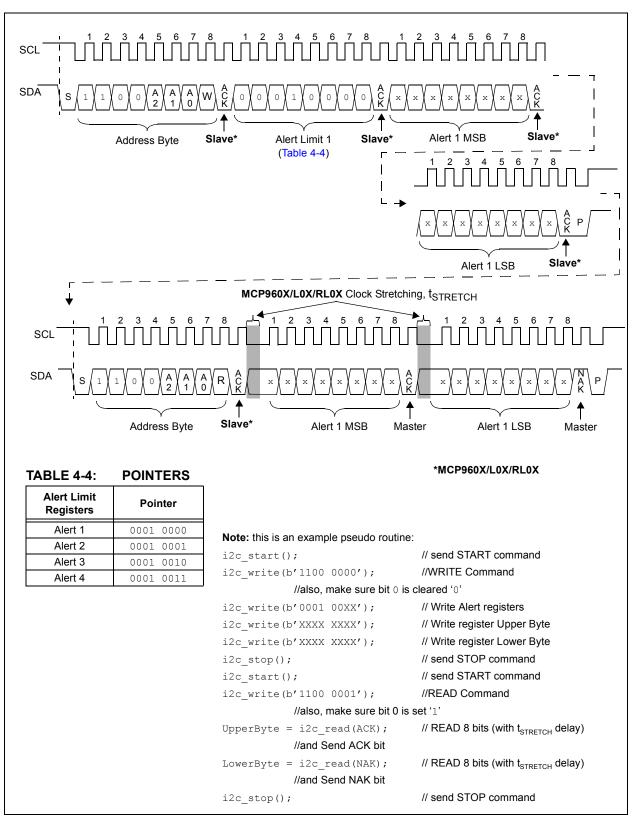


FIGURE 4-5:

Timing Diagram to Set a Register Pointer, Write Two Bytes, and Read the Data.

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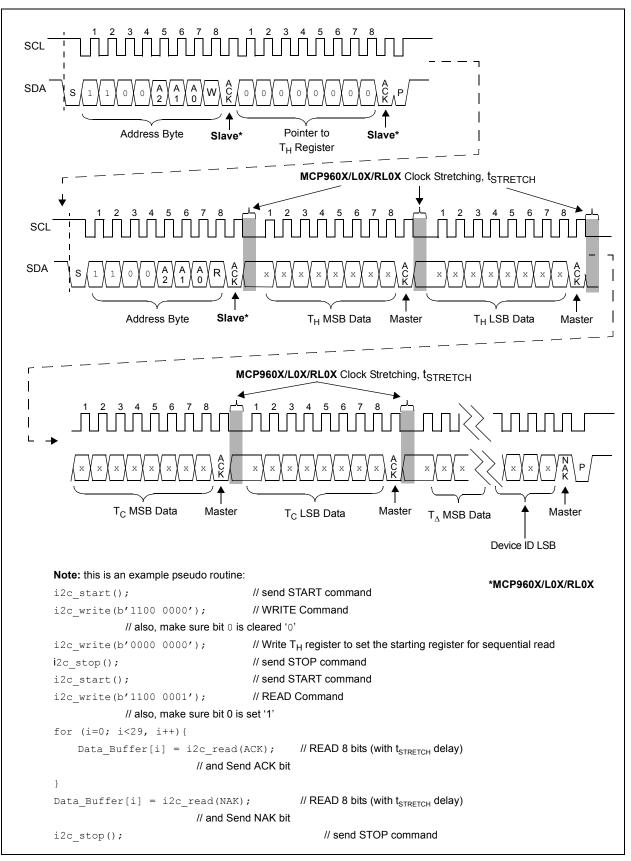
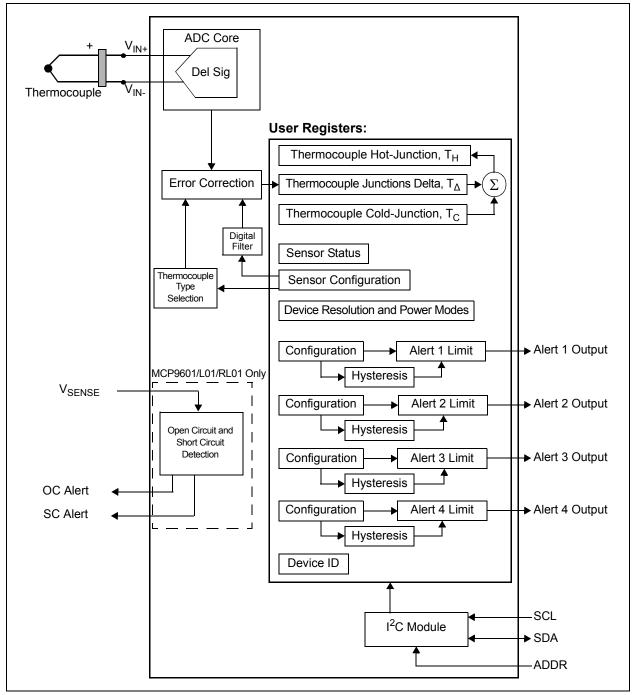


FIGURE 4-6: Timing Diagram to Sequential Read All Registers Starting from T_H Register.

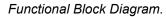
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5.0 FUNCTIONAL DESCRIPTION

The MCP960X/L0X/RL0X temperature sensor consists of an 18-bit Delta-Sigma Analog-to-Digital Converter (ADC), which is used to measure the thermocouple voltage or EMF, a digital temperature sensor used to measure cold-junction or ambient temperature and a processor core which is used to compute the EMF to degree Celsius conversion using coefficients derived from the NIST ITS-90 coefficients. Figure 5-1 shows a block diagram of how these functions are structured in the device.







The MCP960X/L0X/RL0X device has several registers that are user-accessible. These registers include the Thermocouple Temperature (cold-junction compensated), Hot-Junction Temperature, Cold-Junction Temperature, Raw ADC Data, user-programmable Alert Limit registers, and STATUS and Configuration registers.

The Temperature and the Raw ADC Data registers are read-only registers, used to access the thermocouple and the ambient temperature data. In addition, the four Alert Temperature registers are individually controlled, and can be used to detect a rising and/or a falling temperature change. If the ambient temperature drifts beyond the user-specified limits, the MCP960X/L0X/RL0X device outputs an alert flag at the corresponding pin (refer to Section 5.3.3 "Alert Configuration Registers"). The alert limits can also be used to detect critical temperature events.

Unimplemented: Read as '0'

The MCP960X/L0X/RL0X also provides STATUS and Configuration registers, which allow users to detect device statuses. The Configuration registers provide various features, such as adjustable temperature measurement resolution and Shutdown modes. The thermocouple types can also be selected using the Configuration registers.

The registers are accessed by sending a Register Pointer to the MCP960X/L0X/RL0X using the serial interface. This is an 8-bit write-only pointer. Register 5-1 describes the pointer definitions.

REGISTER 5-1: REGISTER POINTER

bit 7-6

U-0	U-0	W-0	W-0	W-0	W-0	W-0	W-0
—	—			P[5:0]		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit	, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 5-0	P[5:0]: Pointer bits
	0000 0000 = Thermocouple Hot-Junction register, T _H
	0000 0001 = Junctions Temperature Delta register, T_{Δ}
	0000 0010 = Cold-Junction Temperature register, T _C
	0000 0011 = Raw ADC Data register
	0000 0100 = STATUS register
	0000 0101 = Thermocouple Sensor Configuration register
	0000 0110 = Device Configuration register
	0000 1000 = Alert 1 Configuration register
	0000 1001 = Alert 2 Configuration register
	0000 1010 = Alert 3 Configuration register
	0000 1011 = Alert 4 Configuration register
	0000 1100 = Alert 1 Hysteresis register, T_{HYST1}
	0000 1101 = Alert 2 Hysteresis register, T_{HYST2}
	0000 1110 = Alert 3 Hysteresis register, T_{HYST3}
	0000 1111 = Alert 4 Hysteresis register , T _{HYST4}
	0001 0000 = Temperature Alert 1 Limit register, T _{ALERT1}
	0001 0001 = Temperature Alert 2 Limit register, T _{ALERT2}
	0001 0010 = Temperature Alert 3 Limit register, T _{ALERT3}
	0001 0011 = Temperature Alert 4 Limit register, T _{ALERT4}
	0010 0000 = Device ID/Revision register

Register	Pointer	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
Hot-Junction	00000000	SIGN	1024°C	512°C	256°C	128°C	64°C	32°C	16°C
Temperature – T _H		8°C	4°C	2°C	1°C	0.5°C	0.25°C	0.125°C	0.0625°C
Junctions Temperature	0000001	SIGN	1024°C	512°C	256°C	128°C	64°C	32°C	16°C
Delta – T $_{\Delta}$		8°C	4°C	2°C	1°C	0.5°C	0.25°C	0.125°C	0.0625°C
Cold-Junction	00000010			SIGN		128°C	64°C	32°C	16°C
Temperature – T _C		8°C	4°C	2°C	1°C	0.5°C	0.25°C	0.125°C	0.0625°C
Raw Data ADC	00000011		SIGN					bit 17	bit 16
		bit 15	_	_	_	_	—	—	bit 8
		bit 7	_	_	_	_	—	_	bit 0
STATUS MCP9600/L00/RL00	00000100	Burst Complete	T _H Update		Input Range	Alert 4 Status	Alert 3 Status	Alert 2 Status	Alert 1 Status
STATUS MCP9601/L01/RL01				Short Circuit (SC)	Open Circuit (OC)/Input Range				
Thermocouple Sensor Configuration	00000101	—	Thermocouple Type Select Type K, J, T, N, S, E, B, R			—	Filter Coefficients		S
Device Configuration	00000110	Cold-Junc. Resolution	ADC R	ADC Resolution Burst		e Temperature Samples		Shutdown Modes	
Alert 1 Configuration	00001000	Interrupt	—	—	Monitor T _H	Detect Ris-	Active- High	Comparator	Enable
Alert 2 Configuration	00001001	Clear			or T _C	ing or Fall- ing Temps	or Active-Low Output	or Interrupt Mode	Alert Output
Alert 3 Configuration	00001010					ing rompo			
Alert 4 Configuration	00001011								
Alert 1 Hysteresis	00001100	128°C	64°C	32°C	16°C	8°C	4°C	2°C	1°C
Alert 2 Hysteresis	00001101								
Alert 3 Hysteresis	00001110								
Alert 4 Hysteresis	00001111								
Alert 1 Limit	00010000	SIGN	1024°C	512°C	256°C	128°C	64°C	32°C	16°C
		8°C	4°C	2°C	1°C	0.5°C	0.25°C	—	_
Alert 2 Limit	00010001	SIGN	1024°C	512°C	256°C	128°C	64°C	32°C	16°C
		8°C	4°C	2°C	1°C	0.5°C	0.25°C	—	_
Alert 3 Limit	00010010	SIGN	1024°C	512°C	256°C	128°C	64°C	32°C	16°C
		8°C	4°C	2°C	1°C	0.5°C	0.25°C	_	_
Alert 4 Limit	00010011	SIGN	1024°C	512°C	256°C	128°C	64°C	32°C	16°C
		8°C	4°C	2°C	1°C	0.5°C	0.25°C	—	_
Device ID/Revision	00100000	0	1	0	0	0	0	0	0
			Revisi	on ID Major			Revision	ID Minor	

TABLE 5-1:	SUMMARY OF REGISTERS AND BIT ASSIGNMENTS

5.1 Thermocouple Temperature Sensor Registers

This device integrates three Temperature registers that are used to read the cold and hot-junction temperatures, and the sum of the two junctions to output the absolute thermocouple temperature. In addition, the Raw ADC Data register, which is used to derive the thermocouple temperature, is available. The following sections describe each register in detail.

5.1.1 THERMOCOUPLE TEMPERATURE REGISTER (T_H)

This register contains the cold-junction compensated and error-corrected thermocouple temperature in degree Celsius. The temperature data from this register is the absolute Thermocouple Hot-Junction temperature, T_H, to the specified accuracy (see **Section 1.0 "Electrical Characteristics**". T_H is the sum of the values in the T_Δ and T_C registers, as shown in Figure 5-2.

EQUATION 5-1: TEMPERATURE CONVERSION

Temperature $\ge 0^{\circ}C$

 $T_{H} = (UpperByte \ x \ 16 + LowerByte/16)$

Temperature < 0°C

 $T_{H} = (UpperByte \ x \ 16 + LowerByte/16) - 4096$

The temperature bits are in two's complement format; therefore, positive temperature data and negative temperature data are computed differently. Equation 5-1 shows how to convert the binary data to temperature in degree Celsius.

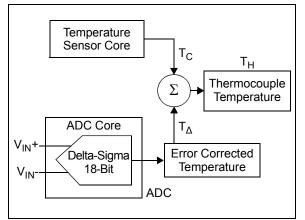


FIGURE 5-2: Thermocouple Temperature Register Block Diagram.

REGISTER 5-2:	THERMOCOUPLE TEMPERATURE REGISTER - T _H (READ-ONLY)
---------------	--

bit 15							bit 8
SIGN	1024°C	512°C	256°C	128°C	64°C	32°C	16°C
R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
8°C	4°C	2°C	1°C	0.5°C	0.25°C	0.125°C	0.0625°C
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 T_{H} : Data in Two's Complement Format. Bit 15 is the sign bit and it is set when the temperature data is less than 0°C.

This register contains the error corrected and cold-junction compensated thermocouple temperature.

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5.1.2 THERMOCOUPLE JUNCTIONS DELTA TEMPERATURE REGISTER (T_{Δ})

This register contains the error corrected Thermocouple Hot-Junction temperature without the Cold-Junction compensation. The error correction methodology uses several coefficients to convert the digitized Thermocouple EMF voltage to degree Celsius. Each Thermocouple type has a unique set of coefficients as specified by NIST, and these coefficients are available in the configuration register for user selection as shown in Figure 5-3.

EQUATION 5-2: TEMPERATURE CONVERSION

Temperature $\ge 0^{\circ}C$

 $T_{\Delta} = (UpperByte \ x \ 16 + LowerByte \ / \ 16)$

Temperature < 0°C

 $T_{\Delta} = (UpperByte \ x \ 16 + LowerByte \ / \ 16) - 4096$

The temperature bits are in two's complement format, therefore, positive temperature data and negative temperature data are computed differently, as shown in Equation 5-2.

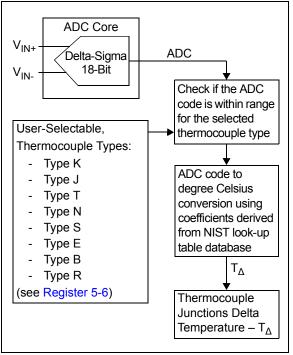


FIGURE 5-3: Thermocouple Hot-Junction Register (T_{Δ}) Block Diagram.

REGISTER 5-3: HOT-JUNCTION TEMPERATURE REGISTER -T_{\(\)} (READ-ONLY)

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
SIGN	1024°C	512°C	256°C	128°C	64°C	32°C	16°C
bit 15					•		bit 8
R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
8°C	4°C	2°C	1°C	0.5°C	0.25°C	0.125°C	0.0625°C
bit 7			•	•			bit 0
Legend:							

	s '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknow	a = Bit is unknown

bit 15-0

T_A: Data in Two's Complement Format. Bit 15 is the sign bit and it is set when the temperature data is less than 0° C.

This register contains Thermocouple Hot-Junction temperature data without the cold-junction compensation.

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5.1.3 COLD-JUNCTION/AMBIENT TEMPERATURE REGISTER (T_C)

The MCP960X/L0X/RL0X integrates an ambient temperature sensor which can be used to measure the thermocouple cold-junction temperature. For accurate measurement, the device will have to be placed at close proximity to the thermocouple cold-junction to detect the junction ambient temperature. This is a 16-bit double-buffered, read-only register. The temperature resolution is user-selectable to 0.0625°C/LSb or 0.25°C/LSb resolutions and setting the resolution determines the temperature update rate, as shown in Table 5-2.

EQUATION 5-3: TEMPERATURE CONVERSION

Temperature $\ge 0^{\circ}C$

 $T_C = (UpperByte \ x \ 16 + LowerByte/16)$

Temperature < 0°C

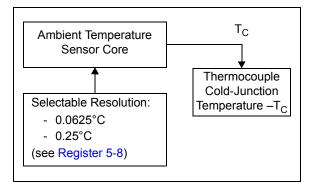
 $T_C = (UpperByte \ x \ 16 + LowerByte/16) - 4096$

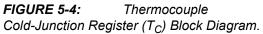
The temperature bits are in two's complement format; therefore, positive temperature data and negative temperature data are computed differently, as shown in Equation 5-3.

TABLE 5-2: RESOLUTION vs. CONVERSION TIME

Resolution	Conversion Time (typical)	Register Bits (Note 1)
0.0625°C	250 ms	SSSS XXXX XXXX XXXX
0.25°C	63 ms	ssss xxxx xxxx xx00
NI. 4. 4. 4	1	6 1 1

Note 1: 's' is Sign and 'x' is unknown bit.





REGISTER 5-4: COLD-JUNCTION TEMPERATURE REGISTER - T_C (READ ONLY)

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	SIG	N		128°C	64°C	32°C	16°C
bit 15							bit 8
R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
8°C	4°C	2°C	1°C	0.5°C	0.25°C	0.125°C	0.0625°C
bit 7							bit (

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	l as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 T_C : Data in Two's Complement Format. Bits 15-12 are sign bits and the bits are set when the temperature data is less than 0°C.

This register contains the thermocouple cold-junction temperature or the device ambient temperature data. Bits 1 and 0 may remain clear ('0') depending on the status of the Resolution setting, bit 7 of Register 5-8.

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5.1.4 ANALOG-TO-DIGITAL CONVERTER (ADC)

The MCP960X/L0X/RL0X uses an 18-bit Delta-Sigma Analog-to-Digital Converter to digitize the Thermocouple EMF voltage and the data is available in the ADC register. The ADC measurement resolution is selectable, which enables the user to choose faster conversion times with reduced resolution. This feature is useful to detect fast transient temperatures.

Resolution/ Sensitivity (typical)	Conversion Time (typical)	Raw ADC Register Bit Format (Note 1)			ster
18-bit/2 µV	320 ms	SSSS	SSSX		XXXX XXXX
16-bit/8 μV	80 ms	SSSS	SSSX	xxxx xxxx	
14-bit/32 µV	20 ms	SSSS	SSSX	xxxx xxxx	xxxx 0000
12-bit/128 μV	5 ms	SSSS	SSSX	xxxx xx00	xxxx 0000

TABLE 5-3:	ADC RESOLUTION ⁽²⁸⁾
------------	--------------------------------

Note 1: 's' is the Sign bit and 'x' is the ADC data bit. 2: See Section 6.2.2 "Conversion Time vs. Self-Heat".

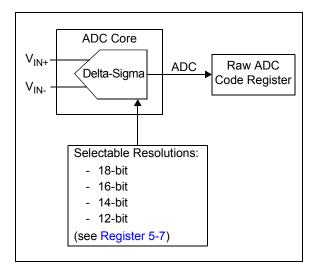


FIGURE 5-5: Delta-Sigma Analog-to-Digital Converter, ADC Core Block Diagram.

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
		SIGN				ADC	Data
bit 23							bit 16
R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
			AD	C Data			
bit 15							bit 8
R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
			AD	C Data			
bit 7							bit 0
Legend:							
R = Readable	bit	W = Writable bit		U = Unimplen	nented bit, re	ead as '0'	
-n = Value at F	POR	'1' = Bit is set		'0' = Bit is clea	ared	x = Bit is unkr	nown

REGISTER 5-5: 24-BIT ADC REGISTER (READ-ONLY)

bit 23-0 **ADC Data:** Raw ADC Raw ADC data in Two's Compliment Format. Bits 23-18 are sign bits and the bits are set when the ADC data is less than 0 micro-volt.

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5.2 Sensor STATUS and Configuration Registers

This device provides various temperature and measurement Status bits which can be monitored regularly by the master controller. In addition, this device integrates various user-programmable features which can be useful to develop complex thermal management applications. The following sections describe each feature in detail.

5.2.1 STATUS REGISTER

The STATUS register contains several flag bits that indicate statuses, such as temperature alert, the ADC input range status for the selected thermocouple type and the Temperature register update status for both single conversion or Burst mode conversions.

R/W-0	R/W-0	U-0	R-0	R-0	R-0	R-0	R-0
Burst Complete	T _H Update	-	Input Range	Alert 4 Status	Alert 3 Status	Alert 2 Status	Alert 1 Status
		Short Circuit (SC) ⁽¹⁾	Open Circuit (OC)/Input Range ⁽¹⁾				
bit 7							bit 0

REGISTER 5-6: STATUS REGISTER

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	d as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7	Burst Complete: Burst Mode Conversions Status Flag bit
	1 = T_{Δ} register Burst mode conversions complete 0 = Writing '0' has no effect Once Burst mode is enabled, this bit is normally set after the first burst is complete. User can clear it and poll the bit periodically until the next burst of temperature conversions is complete (see Register 5-8).
bit 6	T _H Update: Temperature Update Flag bit
	 1 = Temperature conversion complete 0 = Writing '0' has no effect This bit is normally set. User can clear it and poll the bit until the next temperature conversion is complete.
bit 5	Unimplemented: Read as '0' for the MCP9600/L00/RL00 only.
	Short Circuit (SC): Short Circuit Detection bit for the MCP9601/L01/RL01 only (read-only) 1 = Thermocouple Shorted to V_{DD} or V_{SS} 0 = Normal operation The V_{SENSE} pin must be connected to the Thermocouple as indicated in Figure 1-1, using R_A and R_B resistors.

Note 1: MCP9601/L01/RL01 only.

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REGISTER 5-6: STATUS REGISTER (CONTINUED)

bit 4	Input Range: Temperature Range Detection bit (read-only)
	1 = The ADC input Voltage (EMF) or the temperature data from the T _H register exceeds the measure-
	ment range for the selected thermocouple type 0 = The ADC input Voltage (EMF) or the temperature data from the T _H register is within the measure-
	ment range for the selected thermocouple type
	If this bit is set, then the MCP960X/L0X/RL0X input voltage (EMF) to Degree Celsius conversion may be bypassed under these conditions:
	 If the thermocouple EMF exceeds the specified range, then the T_H and T_Δ registers are not updated, but the T_C register is updated with valid temperature data at the specified interval, or t_{CONV}.
	- If the thermocouple EMF is within the specified range, but the sum with the Cold-Junction EMF exceeds the specified range, then the T _H register is not updated, but the T _Δ and T _C registers are updated with valid temperature data at the specified interval, or t _{CONV} . In this case, the value of the T _Δ and T _C registers can be used to calculate valid Hot-Junction Temperature data using the NIST ITS-90 conversion look-up table or polynomial equation.
	 To identify date code for devices with this feature, refer to "MCP9600 Rev. A Silicon Errata and Data Sheet Clarification", DS80000741.
	For the MCP9601/L01/RL01, this bit indicates whether the Thermocouple is disconnected from the inputs. The V _{SENSE} pin must be connected to the Thermocouple as indicated in Figure 1-1, using R _A and R _B resistors. When the Thermocouple is disconnected, the voltage at the inputs exceeds the voltage range for the selected Thermocouple due to the R _A and R _B resistors.
bit 3	Alert 4: Status bit (read-only)
	$1 = T_X > T_{ALERT4}$
	$0 = T_X \leq T_{ALERT4}$
	Where: T_X is either T_H or T_C (user-selectable, see Register 5-10).
bit 2	Alert 3: Status bit (read-only) $1 = T_X > T_{ALERT3}$
	$ = T_X ≤ T_{ALERT3} $ $ 0 = T_X ≤ T_{ALERT3} $ $ Where: T_X is either T_H or T_C (user-selectable, see Register 5-10). $
bit 1	Alert 2: Status bit (read-only)
	$1 = T_X > T_{ALERT2}$ $0 = T_X \le T_{ALERT2}$ Where: T_X is either T_H or T_C (user-selectable, see Register 5-10).
bit 0	Alert 1: Status bit (read-only)
	1 = $T_X > T_{ALERT1}$ 0 = $T_X ≤ T_{ALERT1}$ Where: T_X is either T_H or T_C (user-selectable, see Register 5-10).
Note 1:	MCP9601/L01/RL01 only.

5.2.2 THERMOCOUPLE SENSOR CONFIGURATION REGISTER

The MCP960X/L0X/RL0X Sensor Configuration register is used to select the thermocouple sensor types and to select the digital filter options. This device supports eight thermocouple types. Each type has a unique set of error correction coefficients that are derived from the NIST Thermocouple EMF Voltage Conversion database.

In addition, this device integrates a first order. recursive Infinite Impulse Response (IIR) filter, also known as Exponential Moving Average (EMA). The filter uses the current new temperature sample and the previous filter output to calculate the next filter output. It also adds more weight to the current temperature data, allowing a faster filter response to the immediate change in temperature. This feature can be used to filter out fast thermal transients or thermal instability at the thermocouple hot-junction temperature. Writing this register resets the filter.

The filter equation is shown in Equation 5-4 and the Filter Coefficient n is user-selectable, from Level 0 to 7. A coefficient of 0 disables the filter function and a 7 coefficient provides a maximum digital filter. Figure 5-6 shows the filter response to a step function, which can be used to extrapolate the filter performance to various temperature changes.

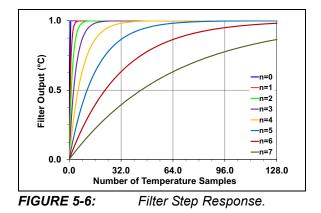
EQUATION 5-4: DIGITAL FILTER

$$Y = k \times X + (1 - k) \times Y_{-1}$$

$$k = 2 \swarrow (2^{n} + 1)$$

Where:

- Y = New filtered temperature in T_{Δ}
- X = Current, unfiltered hot-junction temperatures
- Y₋₁ = Previous filtered temperature
- n = User-selectable filter coefficient



REGISTER 5-7: SENSOR CONFIGURATION REGISTER

U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0
_	Thermocouple Ty	pe Select, Type K,	J, T, N, S, E, B, R	_	Fili	ter Coefficier	nts
bit 7							bit 0
l egend.							

=ogona.			
R = Readable bit	W = Writable bit	U = Unimplemented bit, re	ead as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 Unimplemented: Read as '0'

bit 6-4	Thermocouple Type: Thermocouple Type Select bits 000 = Type K 001 = Type J 010 = Type T 011 = Type N 100 = Type S 101 = Type E 110 = Type B 111 = Type R
bit 3	Unimplemented: Read as '0'
bit 2-0	Filter Coefficient – n: Filter Coefficient bits
	000 = n = 0: Filter off
	001 = n = 1: Minimum filter
	010 = n = 2
	011 = n = 3
	100 = n = 4: Mid filter
	101 = n = 5
	110 = n = 6
	111 = n = 7: Maximum filter

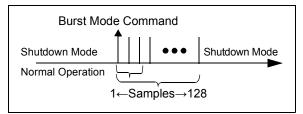
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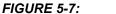
5.2.3 DEVICE CONFIGURATION REGISTER

The device Configuration register allows the user to configure various functions, such as sensor measurement resolutions and Power modes. The Resolution register is used to select the sensor resolution for the desired temperature conversion time. When resolutions are changed, the change takes effect when the next measurement cycle begins.

This device integrates two Low-Power Operating modes: Shutdown mode and Burst mode, which can be selected using bit 0 and bit 1. When the Shutdown mode is executed, all power consuming activities are disabled and the operating current remains at I_{SHDN} . During the Shutdown mode, all registers are accessible; however, I^2C activity on the bus increases the current.

The Burst mode enables users to execute a given number of temperature samples (defined by bits[4-2]) before entering Shutdown mode. Each temperature sample is compared to the user-settable alert temperature limits, and if the alert conditions are true, then the device asserts the corresponding alert output. In addition, if the filter option is enabled, then the filter engine is applied to each temperature sample. The alert thresholds are also compared to the filtered temperature data. This feature is useful for battery power applications, where temperature is sampled upon request from the master controller.





Burst Mode Operation.

REGISTER 5-8: DEVICE CONFIGURATION REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
Cold-Junction Resolution	ADC Measurer	nent Resolution	Burst Moo	le Temperatu	ire Samples	Shutdow	n Modes
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented b	it, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7	Cold-Junction/Ambient Sensor Resolution: Cold-Junction Resolution bit (see Table 5-2): 0 = 0.0625°C 1 = 0.25°C
bit 6-5	ADC Measurement Resolution: ADC Resolution bits (see Table 5-3): 00 =18-bit Resolution 01 =16-bit Resolution 10 =14-bit Resolution 11 =12-bit Resolution
bit 4-2	Burst Mode Temperature Samples: Number of Temperature Samples bits 000 = 1 sample 001 = 2 samples 010 = 4 samples 011 = 8 samples 100 = 16 samples 101 = 32 samples 110 = 64 samples 111 = 128 samples
bit 1-0	Shutdown Modes: Shutdown Mode bits 00 = Normal operation 01 = Shutdown mode 10 = Burst mode 11 = Unimplemented: this setting has no effect

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5.3 Temperature Alert Registers

This device provides four Temperature Alert registers that are individually configured, which allow users to monitor multiple temperature zones with a single device. The following sections describe each alert feature in detail.

5.3.1 ALERT LIMIT REGISTERS

This device integrates four individually controlled Temperature Alert Limit registers. Each alert limit is individually set to detect a rising or falling temperature, or either the Thermocouple Temperature (T_H) register or the Cold-Junction (T_C) register. The corresponding alert limit outputs can also be enabled for temperature status indicators. All alert functions are configured using the Alert Limit Configuration registers (Register 5-11) and the alert output hysteresis function is set using the Alert Hysteresis registers (Register 5-10).

TABLE 5-4: ALERT LIMIT REGISTERS

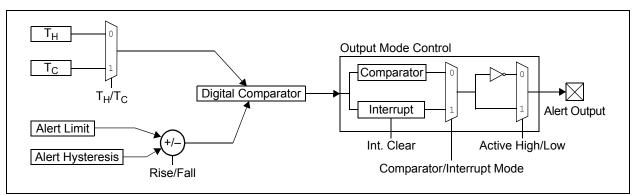
Register	Register Pointer
Alert 1 Limit – T _{ALERT1}	0001 0000
Alert 2 Limit – T _{ALERT2}	0001 0001
Alert 3 Limit – T _{ALERT3}	0001 0010
Alert 4 Limit – T _{ALERT4}	0001 0011

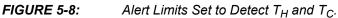
REGISTER 5-9: ALERT LIMITS 1, 2, 3 AND 4 REGISTERS

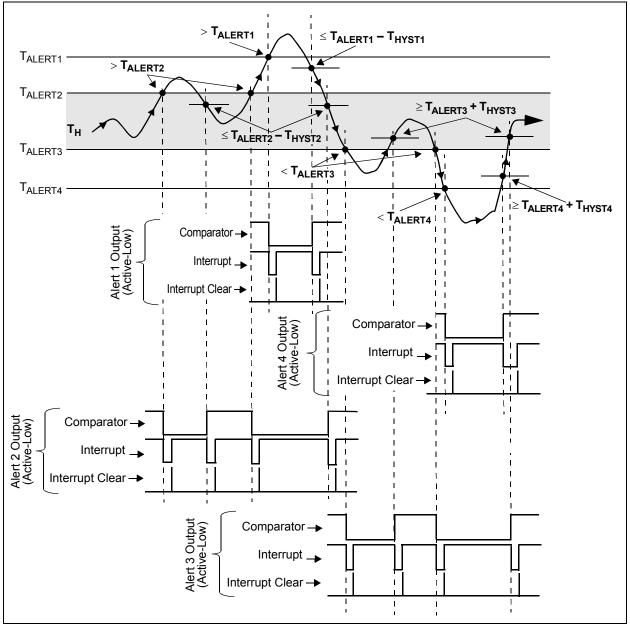
-n = Value at POR (1' = Bit is set (0' = Bit is cleared x = Bit is unkn			nown				
R = Readable	bit	W = Writable	bit	U = Unimpler	mented bit, read	l as '0'	
Legend:							
bit 7							bit 0
8°C	4°C	2°C	1°C	0.5°C	0.25°C		—
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
bit 15							bit 8
SIGN	1024°C	512°C	255°C	128°C	64°C	32°C	16°C
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0

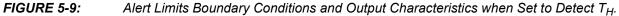
bit 15-0 Alert 1, 2, 3 and 4: Data in Two's Complement Format. Bit 15 is the sign bit and it is set when the temperature data is less than 0°C. Bits 1 and 0 are unimplemented, therefore, writing these bits has no effect.

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5.3.2 ALERT HYSTERESIS REGISTER

This device integrates four individually controlled temperature Alert Hysteresis registers for each alert output, with a range of 0° C to +255°C.

The alert hysteresis directions are set using bit 3 of the corresponding Alert Configuration registers (Register 5-10) to detect rising or falling temperatures. For rising temperatures, the hysteresis range is below the alert limit where, as for falling temperatures, the hysteresis range is above the alert limit, as shown in Figure 5-10.

-n = Value at POR

TABLE 5-5: ALERT HYSTERESIS REGISTERS

	-
Register	Register Pointer
Alert 1 Hysteresis – T _{HYST1}	0000 1100
Alert 2 Hysteresis – T _{HYST2}	0000 1101
Alert 3 Hysteresis – T _{HYST3}	0000 1110
Alert 4 Hysteresis – T _{HYST4}	0000 1111

x = Bit is unknown

REGISTER 5-10: T_{HYSTx}: ALERT 1, 2, 3 AND 4 HYSTERESIS REGISTERS

'1' = Bit is set

				U = Unimpler			
Legend:							
bit 7							bit 0
128°C	64°C	32°C	16°C	8°C	4°C	2°C	1°C
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0	R-0

'0' = Bit is cleared

bit 7-0 Alert Hysteresis: Alert Hysteresis Range 0x00 to 0xFF bits (which represents +1°C to +255°C)

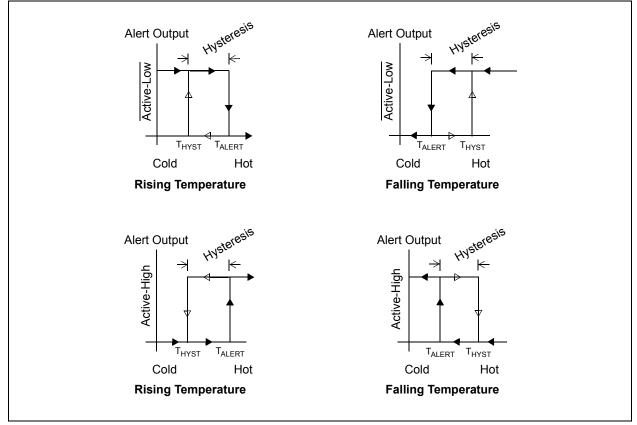


FIGURE 5-10: Graphical Description of Alert Output Hysteresis Direction.

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5.3.3 ALERT CONFIGURATION REGISTERS

This device integrates four individually controlled temperature alert outputs. Each output is configured for the corresponding alert output using the Alert Output Configuration registers.

The Configuration registers are used to enable each output, select the Alert Function mode as Comparator or Interrupt mode, active-high or active-low output, detect rising or falling temperatures and detect T_H or T_C Temperature registers.

The Comparator mode is useful for thermostat-type applications, such as on/off switches for fan controllers, buzzer or LED indicators. The alert output asserts and deasserts when the temperature exceeds the user-specified limit, and the user-specified hysteresis limit. The Interrupt mode is useful for interrupt driven microcontroller-based systems. The alert outputs are asserted each time the temperature exceeds the user-specified alert limit and hysteresis limits. The microcontroller will have Acknowledged the interrupt signal from the corresponding alert output by clearing the interrupt using bit 7 of the corresponding Configuration register.

The Rise/Fall bit (bit 3) and the Monitor T_H/T_C bit (bit 4) can be used to detect and maintain the thermocouple temperature or the cold-junction temperature to the desired temperature window.

TABLE 5-6: ALERT CONFIGURATION REGISTERS

Register	Register Pointer
Alert 1 Configuration	0000 1000
Alert 2 Configuration	0000 1001
Alert 3 Configuration	0000 1010
Alert 4 Configuration	0000 1011

REGISTER 5-11: ALERT 1, 2, 3 AND 4 CONFIGURATION REGISTER

R/W-0	U-0	U-0	R/W-0	R/W-0	R-0	R-0	R-0
Interrupt Clear	—	—	Monitor T_H/T_C	Rise/Fall	Active-High/Low	Comp/Int.	Alert Enable
bit 7							bit 0

Legend:							
R = Readable bit W = Writable bit		W = Writable bit	U = Unimplemented bit, read as '0'				
-n = Value	at POR	'1' = Bit is set	'0' = Bit is cleared x = Bit is unknown				
bit 7	1 = Clea	t Clear: Interrupt Clear bit ars Interrupt flag (forced '0' by mal state or cleared state	device)				
bit 6-5	Unimple	mented: Read as '0'					
bit 4	1 = Aler	T_H or T_C : Temperature Maint t monitor for T_C cold-junction a t monitor for T_H thermocouple	sensor				
bit 3	1 = Aler	I: Alert Temperature Direction t limit for rising or heating tem t limit for falling or cooling tem	peratures				
bit 2	Active-High/Low: Alert State bit 1 = Active-high 0 = Active-low						
bit 1	Comp./Int.: Alert Mode bit 1 = Interrupt mode: Interrupt clears bit (bit 7) – must be set to deassert the ale 0 = Comparator mode						
bit 0	1 = Aler	able: Alert Output Enable bit t output is enabled t output is disabled					

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5.3.4 DEVICE ID AND REVISION ID REGISTER

The Device ID (Identification) and Revision ID register is a 16-bit read-only register, which can be used to identify this device among other devices on the I^2C bus. The upper 8 bits indicate the Device ID of 0x40 for the MCP9600/L00/RL00 and 0x41 for the MCP9601/L01/RL01 respectively, while the lower 8 bits indicate the device revision. The device revision byte is divided into nibbles, where the upper nibble indicates the major revision and the lower nibble indicates minor revisions for each major revision. The initial release is indicated by a major revision of '1' and a minor revision of '0' or 0x4010 for the MCP9600/L00/RL00 and 0x4110 for the MCP9601/L01/RL01. (Refer to "MCP9600 Rev. A Silicon Errata and Data Sheet Clarification", DS80000741, for changes and revision IDs).

REGISTER 5-12: MCP9600/L00/RL00 DEVICE ID AND REVISION ID REGISTER

R-0	R-1	R-0	R-0	R-0	R-0	R-0	R-0
			De	vice ID			
bit 15							bit 8
R-0	R-0	R-0	R-1	R-0	R-0	R-0	R-0
Major				Minor			
bit 7							bit 0
Legend:							
R = Readable bi	R = Readable bit W = Writable bit			U = Unimplemented bit, read as '0'			
-n = Value at PC	R	'1' = Bit is set		'0' = Bit is cleare	d	x = Bit is unkr	nown

bit 15-8 **Device ID:** Device ID bits (0x40)

bit 7-0 **Revision:** Major/Minor Revision ID bits (0x10) for the initial Release, or Revision 1.0 (Refer to the Silicon Errata, DS80000741, for change date codes and revision IDs).

REGISTER 5-13: MCP9601/L01/RL01 DEVICE ID AND REVISION ID REGISTER

R-0	R-1	R-0	R-0	R-0	R-0	R-0	R-1
			Devi	ce ID			
bit 15							bit 8
R-0	R-0	R-0	R-1	R-0	R-0	R-0	R-0
11.0	Maj	_			-	nor	110
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	1 as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Device ID:** Device ID bits (0x41)

bit 7-0 **Revision:** Major/Minor Revision ID bits (0x10) for the initial Release, or Revision 1.0 (Refer to the Silicon Errata, DS80000741, for change date codes and revision IDs).

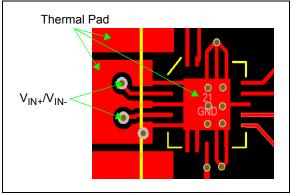
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6.0 APPLICATION INFORMATION

6.1 Layout Considerations

The MCP960X/L0X/RL0X does not require any additional components to digitize thermocouples. However, it is recommended that a decoupling capacitor of 0.1 μ F to 1 μ F be used between the V_{DD} and GND pins. A high-frequency ceramic capacitor is recommended. It is necessary for the capacitor to be located as close as possible to the V_{DD} and ground pins of the device in order to provide effective noise protection.

In addition, good PCB layout is key for better thermal conduction from the PCB temperature to the sensor die. The PCB provides thermal conduction from the die to the thermocouple cold-junction; therefore, the component placement positioning and the copper layout techniques are key for optimum cold-junction compensation. The recommended implementation for optimum temperature sensitivity is to extend a copper ground pad around the device pins, as shown in Figure 6-1.





Recommended PCB Layout.

6.1.1 COLD-JUNCTION COMPENSATION

Copper provides better thermal conductivity than PCB FR4 to the ambient temperature. It also provides better thermal conduction than the 5 mm x 5 mm MQFN plastic package, which houses the temperature sensor die. Therefore, when connecting the thermocouple wire to the PCB, it is recommended to place the ground copper between the thermocouple connector footprint, where dissimilar conductive material is attached to the PCB and the MCP960X/L0X/RL0X exposed pad. This allows temperature to stabilize to the local ambient temperature (between the thermocouple connector junction and the PCB copper) and the copper trace conducts the temperature to the package exposed pad where the temperature sensor die is placed. The placement of the sensor exposed pad to the thermocouple connector junction greatly determines the temperature sensor's sensitivity to the local junction temperature changes. Figure 6-2 demonstrates the recommended techniques.

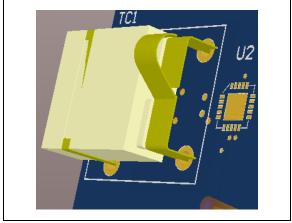


FIGURE 6-2: Recommended Component Placement.

6.2 Thermal Considerations

The potential for self-heating errors exist if the MCP960X/L0X/RL0X SDA, SCL and alert outputs are heavily loaded (high current) with pull-up resistors and circuits, such as high-current LEDs or buzzer loads. The temperature rise due to self-heat increases the ambient temperature sensor output, resulting in an increased temperature offset error compared to the thermocouple cold-junction ambient temperature.

6.2.1 SELF-HEAT DURING OPERATION

During normal operation, the typical self-heating error is negligible due to the relatively small current consumption of the MCP960X/L0X/RL0X. However, this device integrates a processor to compute the equations necessary to convert the thermocouple EMF voltage to degrees Celsius. The processor also maintains the I²C bus. During I²C communication, the device operating current increases to I_{DD} = 1.5 mA (typical), I²C Active specification. If the bus is continually polled for data at frequent intervals, then the processor power dissipates heat to the temperature sensor and the effect of self-heat can be detected. Therefore, the recommended implementation is to maintain polling to no more than three times per temperature conversion period of 320 ms or use the Burst mode feature to manage self-heat (refer to Section 6.2.3 "Using Burst Mode to Manage Self-Heat"). Equation 6-1 can also be used to determine the effect of self-heat.

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EQUATION 6-1: EFFECT OF SELF-HEATING

	$T_{\Delta} = \theta_{JA}(V_{DD} \bullet I_{DD})$ $T_{\Delta} = \theta_{JC}(V_{DD} \bullet I_{DD})$
	$\Delta JC^* DD^* DD^*$
	$T_{\Delta} = T_J - T_A$
Where	:
Т _Ј =	= Junction Temperature
T _A =	- Ambient Temperature
θ _{JA} =	 Package Thermal Resistance: Junction to Ambient
θ _{JC} =	 Package Thermal Resistance: Junction to Case

At room temperature ($T_A = +25^{\circ}C$) with $I_{DD} = 2.5$ mA (maximum) and $V_{DD} = 3.3V$, the self-heating due to power dissipation, T_{Δ} , is 0.32°C for the MQFN package.

6.2.2 CONVERSION TIME vs. SELF-HEAT

Once the ADC completes digitization, the processor initiates the data computation routine for t_{CALC} , which also increases I_{DD} . During the 18-bit ADC conversion time (3 SPS, Samples per Second), the increased current lasts for approximately 5% of the one-second period. The effect of self-heat for the total power consumed per second, including the 5% t_{CALC} period, is negligible. However, as the ADC resolution is reduced from 18-bit to 16-bit, the power consuming t_{CALC} period increases to 20% per second. This change in resolution adds approximately 0.04°C (typical) temperature error due to self-heat. Table 6-1 provides an estimate for self-heat for all resolutions using Equation 6-1.

In order to reduce the effects of self-heat for lower resolution settings, the Burst mode feature is recommended to manage the effects of self-heat.

TABLE 6-1: ADC RESOLUTION vs. SELF-HEAT

Resolution	SPS (typ.)	t _{CALC} Duration per Second	\mathbf{T}_{Δ}
18-bit	3	5%	0.0096°C
16-bit	15	20%	0.0384°C
14-bit	60	80%	0.1536°C
12-bit	240	100%	0.1920°C

Note: V_{DD} = 3.3V and I_{DD} = 1.5 mA (typical).

6.2.3 USING BURST MODE TO MANAGE SELF-HEAT

The Burst mode feature is useful to manage power dissipation while maintaining the device sensitivity to changes in temperature (see Section 5.2.3 "Device Configuration Register"). While the device is in Low-Power or Shutdown mode, the master controller executes Burst mode to sample temperature. The number of temperature samples and the measurement resolution settings are selected while executing the command. While in Burst mode, if the temperature data exceeds the alert limits, the device asserts the corresponding alert output. The alert outputs are used so the master controller does not need to continually poll the latest temperature data and potentially increase the temperature error.

In addition, with some applications monitoring several hundred degrees of temperature changes, 18-bit resolution may not be necessary. In this case, a fewer number of burst samples reducing the resolution enables the user to monitor fast transient temperatures at the burst intervals. The 12-bit ADC resolution provides approximately 3°C resolution (for Type K) and a new sample of temperature data is computed at approximately 20 ms intervals. Therefore, the number of Burst mode Samples per Second can be selected to manage the effects of self-heat using these estimates.

The temperature conversion status during Burst mode can also be momentarily polled (using bit 7 of Register 5-6) to detect whether the on-going sample bursts are completed. The master controller may terminate an on-going burst by executing a shutdown command or resetting the Burst mode by sending another burst command.

6.2.4 ALERT OUTPUTS

The alert outputs are intended to drive high-impedance loads. Typically, the outputs are connected to a microcontroller input pin. However, if the outputs are used to drive indicators, such as LEDs or buzzers, then a buffer circuit is recommended in order to minimize the effects of self-heat due to the applied load (see Figure 6-3).

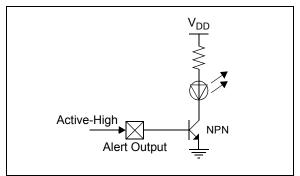


FIGURE 6-3: Indicator.

Alert Output Buffer for LED

6.3 Device Features

6.3.1 I²C ADDRESSING

The MCP960X/L0X/RL0X supports up to eight devices on the I²C bus. Applications, such as large thermal management racks with several thermocouple sensor interfaces, are able to monitor various temperature zones with minimal pin count microcontrollers. This reduces the total solution cost, while providing a highly accurate thermal management solution using the MCP960X/L0X/RL0X.

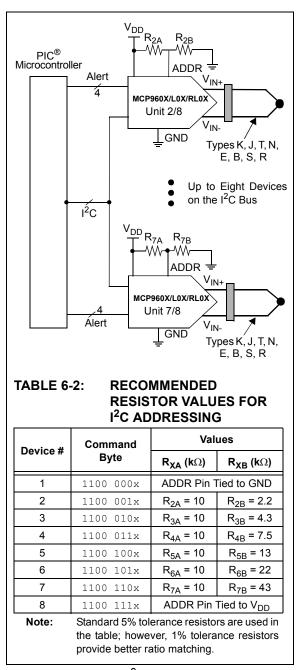


FIGURE 6-4: I²C Address Selection Implementation.

6.3.2 INPUT IMPEDANCE

The MCP960X/L0X/RL0X uses a switched capacitor amplifier input stage to gain the input signal to a maximum resolution of 2 μ V/LSb at an 18-bit ADC setting. An internal input capacitor is used for charge storage. The differential input impedance, Z_{IN_DF} , is dominated by the sampling capacitor and the switched capacitor amplifier sampling frequency. During a sampling period, the charging and discharging of the sampling capacitor creates dynamic input currents at the input pins. Adding a 10-100 nF capacitor between the inputs can improve stability.

Since the sampling capacitor is only switching to the input pins during a conversion process, the input impedance is only valid during conversion periods. During Low-Power or Shutdown mode, the input amplifier stage is disabled; therefore, the input impedance is Z_{IN_CM} , which is due to the leakage current from ESD protection diodes, as shown in Figure 6-5.

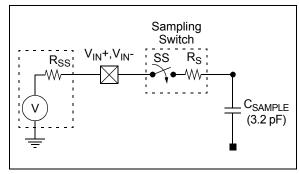


FIGURE 6-5:

Thermocouple Input Stage.

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MCP960X/L0X/RL0X

6.3.3 OPEN AND SHORT DETECTION CIRCUITS

The MCP9601/L01/RL01 has a Thermocouple open and short circuit detection mechanism, which is implemented using a Sense-Input pin (V_{SENSE}), as shown in Figure 1-1. The V_{SENSE} pin and R_A and R_B resistors must be connected as indicated in Figure 1-1. For proper operation, the resistor values must also be within the specified range. When open circuit or short circuit conditions are detected, the OC Alert and SC Alert Active-High Push-Pull outputs are asserted, respectively.

For the MCP9600/L00/RL00, external circuits can be added to detect the thermocouple status as open (physically disconnected) or as short (thermocouple wire in contact with the system ground or V_{DD}). If a passive circuit is added to the input stage, then the circuit loading effect to the MCP9600/L00/RL00 ADC inputs must be considered. System calibration is also required to ensure proper accuracy. In addition, external loads can degrade the device performance, such as input offset, gain and Integral Nonlinearity (INL) errors. If a low-impedance active circuit is added, then both offset and gain errors must be calibrated.

6.3.3.1 Open-Circuit Detection Technique

For MCP9600/L00/RL00 open-circuit detection, the Input Range bit (bit 4) of the STATUS register (Register 5-6), can be used to detect open-circuit conditions. This would require a few external resistors, as shown in Figure 6-6. The passive circuit does not affect the MCP9600/L00/RL00 accuracy (the recommended value for R_B is set to 1 MΩ). When the thermocouple is connected, the input Common-mode voltage is $0.5 \times V_{DD}$. When the thermocouple is disconnected, the voltage at the V_{IN+} input is $0.66 \times V_{DD}$ and the voltage at the V_{IN+} input is pulled down to V_{SS} . This change forces the Input Range bit to be set.

The MCP9601/L01/RL01 open-circuit detection mechanism operates similarly (see Figure 6-7), and the detection thresholds are specified as V_{SiOC} and V_{SiNOR} (see **DC Characteristics**).

The master controller can momentarily poll the Status bit to detect the Open-Circuit condition. For the MCP9601/L01/RL01, the OC Alert pin can are used as hardware indicator.

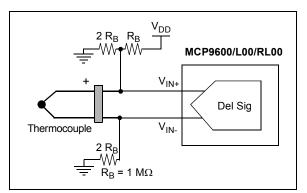


FIGURE 6-6: Adding Open-Circuit Detection Resistors (MCP9600/L00/RL00).

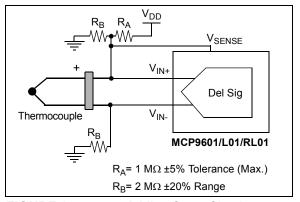
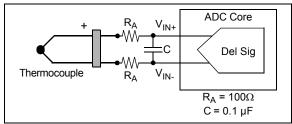


FIGURE 6-7: Adding Open-Circuit Detection Resistors (MCP9601/L01/RL01).

6.3.4 ALIASING AND ANTI-ALIASING FILTER

Aliasing occurs when the input signal contains time varying signals with frequency greater than half the sample rate. In the aliasing conditions, the ADC can output unexpected codes. The ADC integrates a first order sync filter; however, an external anti-aliasing filter can provide an added filter for high noise applications. This can be done with a simple RC low-pass filter at the inputs, as shown in Figure 6-8. Open-circuit detection resistors can also be added, as shown in Figure 6-9.





Adding a Low-Pass Filter.

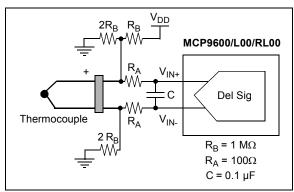


FIGURE 6-9: Adding Open-Circuit Detection Resistors with an Input Low-Pass Filter (MCP9600/L00/RL00, see Section 6.3.3 "Open and Short Detection Circuits").

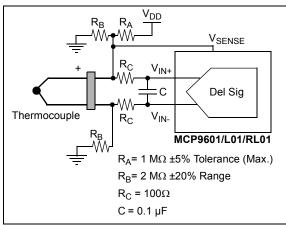
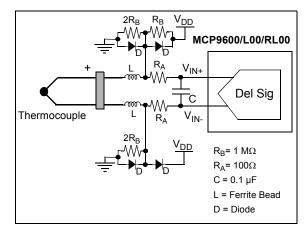
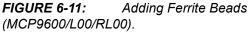


FIGURE 6-10: Adding Open-Circuit Detection Resistors with an Input Low-Pass Filter (MCP9601/L01/RL01).

6.3.5 ESD PROTECTION USING FERRITE BEADS

Ferrite beads are highly recommended to protect the MCP960X/L0X/RL0X and other circuits from ESD discharge through the thermocouple wire. The beads suppress fast transient signals, such as ESD, and can be added in-line to the ADC inputs. In addition, protection diodes are also recommended, as shown in Figure 6-11.





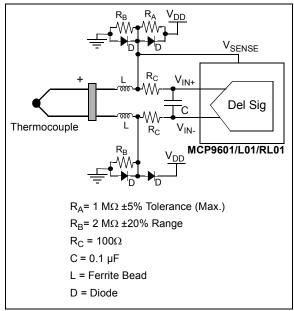
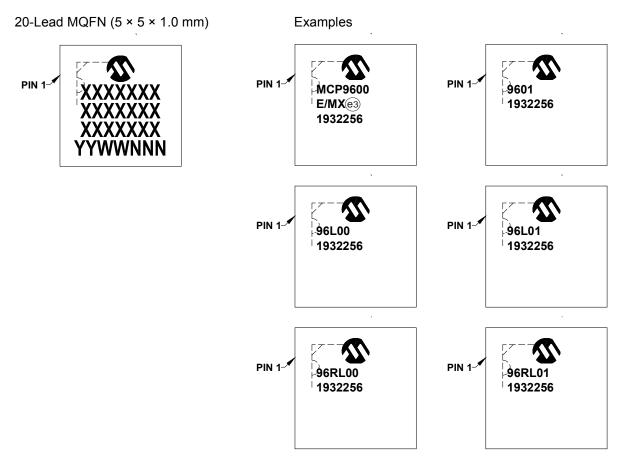


FIGURE 6-12: Adding Ferrite Beads (MCP9601/L01/RL01).

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7.0 PACKAGING INFORMATION

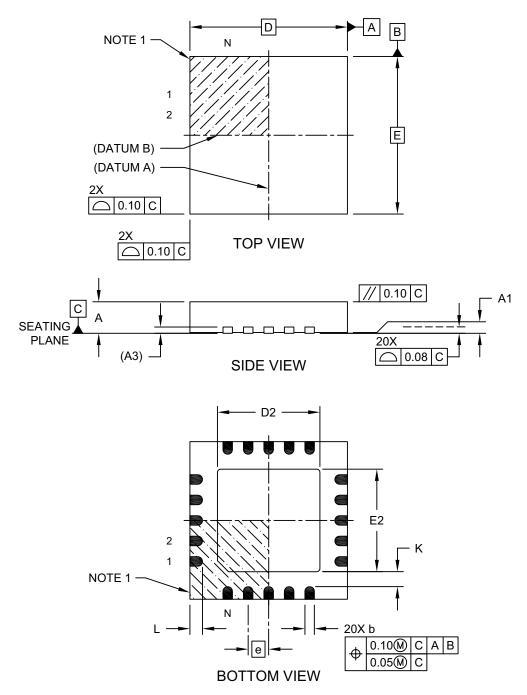
7.1 Package Marking Information



Legend:	XXX Y YY WW NNN @3 *	Customer-specific information Year code (last digit of calendar year) Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code Pb-free JEDEC [®] designator for Matte Tin (Sn) This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
	be carrie	nt the full Microchip part number cannot be marked on one line, it will d over to the next line, thus limiting the number of available s for customer-specific information.

20-Lead More Thin Plastic Quad Flat, No Lead Package (NU) - 5x5x1.0 mm Body [MQFN] - (Also called VQFN)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

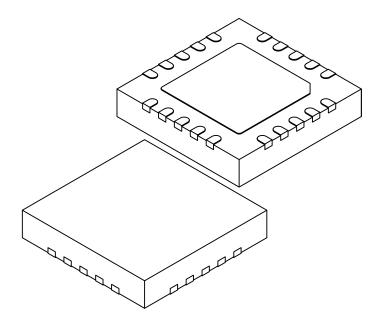


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20-Lead More Thin Plastic Quad Flat, No Lead Package (NU) - 5x5x1.0 mm Body [MQFN] - (Also called VQFN)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS				
Dimension	Limits	MIN	NOM	MAX	
Number of Pins	N	20			
Pitch	е		0.65 BSC		
Overall Height	Α	0.90	0.95	1.00	
Standoff	A1	0.00	0.02	0.05	
Terminal Thickness	A3	0.20 REF			
Overall Length	D	5.00 BSC			
Exposed Pad Length	D2	3.15 3.25 3.35			
Overall Width	E	5.00 BSC			
Exposed Pad Width	E2	3.15	3.25	3.35	
Terminal Width	b	0.25	0.30	0.35	
Terminal Length	L	0.35	0.40	0.45	
Terminal-to-Exposed-Pad	K	0.20	-	-	

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. Package is saw singulated

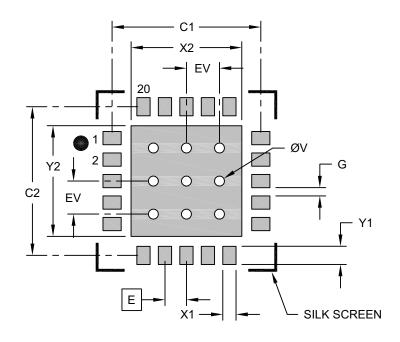
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances. REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-186B Sheet 2 of 2

20-Lead More Thin Plastic Quad Flat, No Lead Package (NU) - 5x5x1.0 mm Body [MQFN] - (Also called VQFN)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	MILLIMETERS			
Dimension	Dimension Limits			MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	X2			3.35
Optional Center Pad Length	Y2	3.3		
Contact Pad Spacing C			4.50	
Contact Pad Spacing	C2		4.50	
Contact Pad Width (X20)	X1	0.4		0.40
Contact Pad Length (X20)	Y1			0.55
Distance Between Pads	G	0.20		
Thermal Via Diameter V			0.30	
Thermal Via Pitch	EV			

Notes:

- 1. Dimensioning and tolerancing per ASME Y14.5M
- BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- 2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

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APPENDIX A: REVISION HISTORY

Revision F (August 2019)

The following is the list of modifications:

1. Added the MCP9601/L01/RL01 device family and related information throughout the document.

Revision E (January 2019)

The following is the list of modifications:

1. Added the MCP96RL00/RL01 device and related information throughout the document.

Revision D (August 2018)

The following is the list of modifications:

1. Added the MCP96L00 device and related information throughout the document.

Revision C (September 2017)

The following is the list of modifications:

- 1. Updated Figure 4-3, Equation 5-1, Equation 5-2 and Equation 5-3.
- 2. Updated Section 6.3.3.1 "Open-Circuit Detection Technique".
- 3. Various typographical edits.

Revision B (June 2016)

The following is the list of modifications:

- 1. Corrected the pin description error for pins 19 and 20 on page 1.
- 2. Added the MCP9600 Evaluation Board picture on page 2.
- 3. Added Section 6.3.3.1 "Open-Circuit Detection Technique" and updated Section 6.3.4 "Aliasing and Anti-Aliasing Filter" and Section 6.3.5 "ESD Protection Using Ferrite Beads".
- 4. Updated the Product Identification System section.

Revision A (August 2015)

· Original release of this document.

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PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO. ⁽¹⁾	[X] ⁽²⁾	×	<u>/XX</u>	Exa	Examples:			
Device	Tape and Reel	Temperature	Package	a)	MCP9600-E/MX:	Extended temperature, 20-lead MQFN package		
	Option	Range		b)	MCP9600T-E/MX:	Tape and Reel, Extended temperature, 20-lead MQFN package		
Device:	MCP9600: MCP9600T:	Signal Conditioning	IC ⁽¹⁾ IC ⁽¹⁾ (Tape and Reel)	C)	MCP96L00-E/MX:	Extended Temperature, 20-lead MQFN package		
	MCP96L00: Signal Condition MCP96L00T: Signal Condition	Signal Conditioning	IC ⁽¹⁾ IC ⁽¹⁾ (Tape and Reel)	d)	MCP96L00T-E/MX:	Tape and Reel, Extended temperature, 20-lead MQFN package		
	MCP9601:	Signal Conditioning	IC ⁽¹⁾ (Tape and Reel) IC ⁽¹⁾	e)	MCP96RL00-E/MX:	Extended temperature, 20-lead MQFN package		
		Signal Conditioning Signal Conditioning	IC ⁽¹⁾ (Tape and Reel)	f)	MCP96RL00T-E/MX:	Tape and Reel, Extended temperature, 20-lead MQFN package		
	MCP96RL01		IC ⁽¹⁾ (Tape and Reel)	g)	MCP9601-E/MX:	Extended temperature, 20-lead MQFN package		
Tape and Reel Option:	T = Tape and	l Reel ⁽²⁾		h)	MCP9601T-E/MX:	Tape and Reel, Extended temperature, 20-lead MQFN package		
Temperature Range:	E = -40°C to	+125°C		i)	MCP96L01-E/MX:	Extended Temperature, 20-lead MQFN package		
Package:	MX = More Thi	n Plastic Quad Flat,	MQFN, 20-Lead	j)	MCP96L01T-E/MX:	Tape and Reel, Extended temperature, 20-lead MQFN package		
				k)	MCP96RL01-E/MX:	Extended temperature, 20-lead MQFN package		
				I)	MCP96RL01T-E/MX:	Tape and Reel, Extended temperature, 20-lead MQFN package		
				Note	features, please	nocouple types or custom contact your local Microchip imum purchase volumes are		
					catalog part num is used for order printed on the de your Microchip S	dentifier only appears in the ber description. This identifie ing purposes and is not evice package. Check with sales Office for package he Tape and Reel option.		

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- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
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